TCA6408A 具有中断输出、复位和配置寄存器的低电压 8 位 I²C 和 SMBus I/O 扩展器

1 特性

- I²C 至并行端口扩展器
- 工作电源电压范围为 1.65 V 至 5.5 V
- 支持 1.8V、2.5V、3.3V 和 5V I²C 总线和 P 端口之间进行双向电平转换和 GPIO 扩展
- 1 µA 的低待机流耗
- 可耐受 5V 电压的 I/O 端口
- 400kHz 快速 I²C 总线
- 硬件地址引脚，允许在同一 I²C/SMBus 总线上支持两个 TCA6408A 器件
- 低电平有效复位 ($\overline{RESET}$) 输入
- 开漏低电平有效中断 ($\overline{INT}$) 输出
- 输入和输出配置寄存器
- 极性反转寄存器
- 内部上电复位
- 加电时所有通道均被配置为输入
- 加电时无干扰
- SCL 和 SDA 输入端装有噪声滤波器
- 具有最大高电流驱动能力的锁存输出，适用于直接驱动 LED
- 闩锁性能超过 100mA，符合 JESD 78 II 类规范的要求
- 施密特触发操作支持在 SCL 和 SDA 输入端实现缓慢输入转换并提升开关噪声抗扰度
- ESD 保护性能超出 JESD 22 标准
  - 2000V 人体放电模型 (A114-A)
  - 1000V 充电器件模型 (C101)

2 应用

- 服务器
- 路由器（电信交换设备）
- 个人计算机
- 个人电子产品（游戏机）
- 工业自动化
- 采用 GPIO 受限处理器的产品

3 说明

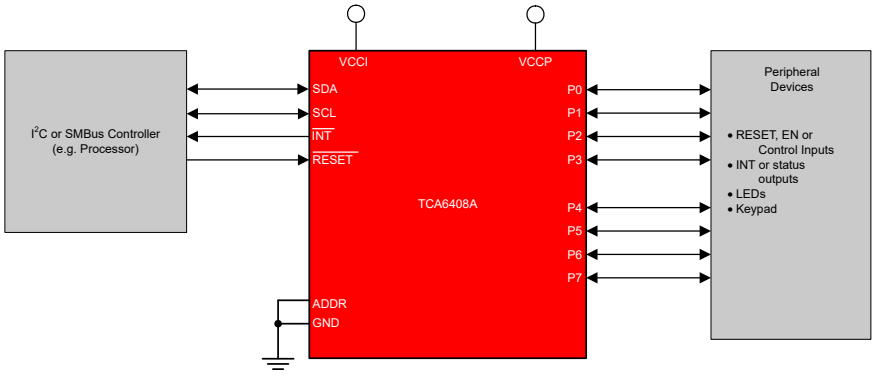
TCA6408A 是一款 16 引脚器件，可为两线双向 I²C 总线（或 SMBus）协议提供 8 位通用并行输入/输出 (I/O) 扩展。在器件运行过程中，I²C 总线侧 (V_{CCI}) 和 P 端口侧 (V_{CCP}) 均可由电压介于 1.65V 至 5.5 V 之间的电源供电。这使得 TCA6408A 能够在 SDA/SCL 侧（在这里，电源电平正在降低以节省电力）与下一代微处理器和微控制器相连接。与微处理器和微控制器的电源电压不断走低不同，有些 PCB 组件（例如 LED）仍然需要使用 5V 电源。

该器件支持 100kHz（标准模式）和 400kHz（快速模式）时钟频率。当开关、传感器、按钮、LED、风扇等设备需要额外使用 I/O 时，I/O 扩展器（如 TCA6408A）可提供简易解决方案。

封装信息

器件型号	封装(1)	封装尺寸（标称值）
TCA6408A	TSSOP (16)	5.00mm × 4.40mm
	VQFN (16)	3.00mm × 3.00mm
	UQFN (16)	2.60mm x 1.80mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



简化版原理图

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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision D (July 2015) to Revision E (January 2023) **Page**

- 将提到 I²C 的旧术语实例通篇更改为控制器和目标 1
- Added paragraph: "Ramping up the device V_{CCP}" to *Power-On Reset Requirements* 31

Changes from Revision C (July 2009) to Revision D (July 2015) **Page**

- 添加了 *引脚配置和功能* 部分、*ESD 等级* 表、*特性说明* 部分、*器件功能模式*、*应用和实施* 部分、*电源相关建议* 部分、*布局* 部分、*器件和文档支持* 部分以及 *机械、封装和可订购信息* 部分 1
- V_{IH} - Split SCL, SDA and $\overline{RESET}$ to different rows in the *Recommended Operating Conditions* table. Max value of SCL, SDA changed From: 5.5 V To: V_{CCI} 5

5 Pin Configuration and Functions

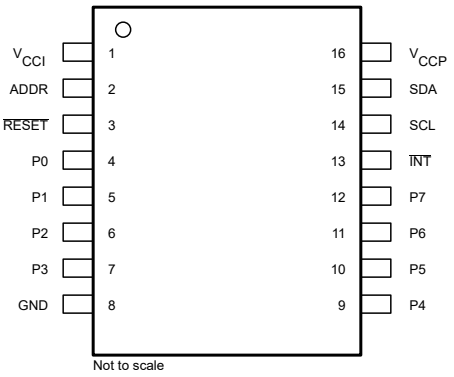


图 5-1. PW Package, 16-Pin TSSOP (Top View)

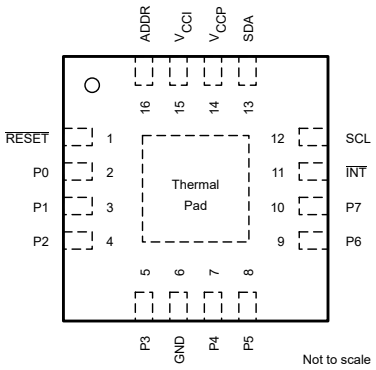


图 5-2. RGT Package, 16-Pin VQFN (Top View)

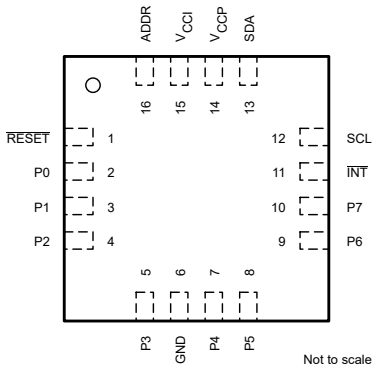


图 5-3. RSV Package, 16-Pin UQFN (Top View)

表 5-1. Pin Functions

PIN			DESCRIPTION
NAME	TSSOP	UQFN, VQFN	
ADDR	2	16	Address input. Connect directly to V_{CCP} or ground.
GND	8	6	Ground
$\overline{INT}$	13	11	Interrupt output. Connect to V_{CCI} through a pull-up resistor.
P0	4	2	P-port input/output (push-pull design structure). At power on, P0 is configured as an input.
P1	5	3	P-port input/output (push-pull design structure). At power on, P1 is configured as an input.
P2	6	4	P-port input/output (push-pull design structure). At power on, P2 is configured as an input.
P3	7	5	P-port input/output (push-pull design structure). At power on, P3 is configured as an input.
P4	9	7	P-port input/output (push-pull design structure). At power on, P4 is configured as an input.

表 5-1. Pin Functions (continued)

PIN			DESCRIPTION
NAME	TSSOP	UQFN, VQFN	
P5	10	8	P-port input/output (push-pull design structure). At power on, P5 is configured as an input.
P6	11	9	P-port input/output (push-pull design structure). At power on, P6 is configured as an input.
P7	12	10	P-port input/output (push-pull design structure). At power on, P7 is configured as an input.
$\overline{\text{RESET}}$	3	1	Active-low reset input. Connect to V_{CCI} through a pull-up resistor, if no active connection is used.
SCL	14	12	Serial clock bus. Connect to V_{CCI} through a pull-up resistor.
SDA	15	13	Serial data bus. Connect to V_{CCI} through a pull-up resistor.
V_{CCI}	1	15	Supply voltage of I^2C bus. Connect directly to the V_{CC} of the external I^2C controller. Provides voltage level translation.
V_{CCP}	16	14	Supply voltage of TCA6408A for P-ports

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (see (1))

				MIN	MAX	UNIT
V_{CCI}	Supply voltage for I^2C pins			–0.5	6.5	V
V_{CCP}	Supply voltage for P-ports			–0.5	6.5	V
V_I	Input voltage(2)			–0.5	6.5	V
V_O	Output voltage(2)			–0.5	6.5	V
I_{IK}	Input clamp current	ADDR, $\overline{RESET}$, SCL	$V_I < 0$		±20	mA
I_{OK}	Output clamp current	$\overline{INT}$	$V_O < 0$		±20	mA
I_{IOK}	Input/output clamp current	P-port	$V_O < 0$ or $V_O > V_{CCP}$		±20	mA
		SDA	$V_O < 0$ or $V_O > V_{CCI}$		±20	
I_{OL}	Continuous output low current	P-port	V_O = 0 to V_{CCP}		50	mA
	Continuous output low current	SDA, $\overline{INT}$	V_O = 0 to V_{CCI}		25	
I_{OH}	Continuous output high current	P-port	V_O = 0 to V_{CCP}		50	mA
I_{CC}	Continuous current through GND				200	mA
	Continuous current through V_{CCP}				160	
	Continuous current through V_{CCI}				10	
T_{stg}	Storage temperature			–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under 节 6.3. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

			MIN	MAX	UNIT
V_{CCI}	Supply voltage for I^2C pins		1.65	5.5	V
V_{CCP}	Supply voltage for P-ports		1.65	5.5	
V_{IH}	High-level input voltage	SCL, SDA	0.7 × V_{CCI}	V_{CCI}	V
		$\overline{RESET}$	0.7 × V_{CCI}	5.5	
		ADDR, P7 – P0	0.7 × V_{CCP}	5.5	
V_{IL}	Low-level input voltage	SCL, SDA, $\overline{RESET}$	–0.5	0.3 × V_{CCI}	V
		ADDR, P7 – P0	–0.5	0.3 × V_{CCP}	
I_{OH}	High-level output current	P7 – P0		10	mA
I_{OL}	Low-level output current	P7 – P0		25	mA
T_A	Operating free-air temperature		–40	85	°C

6.4 Thermal Information

THERMAL METRIC(1)		TCA6408A			UNIT
		PW (TSSOP)	RGT (VQFN)	RSV (UQFN)	
		16 PINS	16 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	122	65.5	127.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	56.4	92.1	62.3	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	67.1	40.0	48.4	°C/W
ψ_{JT}	Junction-to-top characterization parameter	10.8	6.9	2.5	°C/W
ψ_{JB}	Junction-to-board characterization parameter	66.5	21.3	48.6	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

6.5 Electrical Characteristics

over recommended operating free-air temperature range, V_{CCI} = 1.65 V to 5.5 V (unless otherwise noted)

PARAMETER			TEST CONDITIONS	V_{CCP}	MIN	TYP(1)	MAX	UNIT
V_{IK}	Input diode clamp voltage		I_I = – 18 mA	1.65 V to 5.5 V	– 1.2			V
V_{POR}	Power-on reset voltage(2)		V_I = V_{CCP} or GND, I_O = 0	1.65 V to 5.5 V		1	1.4	V
V_{OH}	P-port high-level output voltage		I_{OH} = – 8 mA	1.65 V	1.2			V
				2.3 V	1.8			
				3 V	2.6			
				4.5 V	4.1			
			I_{OH} = – 10 mA	1.65 V	1.1			
				2.3 V	1.7			
				3 V	2.5			
				4.5 V	4.0			
V_{OL}	P-port low-level output voltage		I_{OL} = 8 mA	1.65 V			0.45	V
				2.3 V			0.25	
				3 V			0.25	
				4.5 V			0.2	
			I_{OL} = 10 mA	1.65 V			0.6	
				2.3 V			0.3	
				3 V			0.25	
				4.5 V			0.2	
I_{OL}	SDA		V_{OL} = 0.4 V	1.65 V to 5.5 V	3			mA
	$\overline{INT}$				3	15		
I_I	SCL, SDA, $\overline{RESET}$		V_I = V_{CCI} or GND	1.65 V to 5.5 V			±0.1	µA
	ADDR		V_I = V_{CCP} or GND				±0.1	
I_{IH}	P-port		V_I = V_{CCP}	1.65 V to 5.5 V			1	µA
I_{IL}	P-port		V_I = GND				1	µA
I_{CC} (I_{CCI} + I_{CCP})	Operating mode	SDA, P-port, ADDR, $\overline{RESET}$	V_I on SDA and $\overline{RESET}$= V_{CCI} or GND, V_I on P-port and ADDR = V_{CCP} or GND, I_O = 0, I/O = inputs, f_{SCL} = 400 kHz	3.6 V to 5.5 V		10	20	µA
				2.3 V to 3.6 V		6.5	15	
				1.65 V to 2.3 V		4	9	
	Standby mode	SCL, SDA, P-port, ADDR, $\overline{RESET}$	V_I on SCL, SDA and $\overline{RESET}$ = V_{CCI} or GND, V_I on P-Port and ADDR = V_{CCP} or GND, I_O = 0, I/O = inputs, f_{SCL} = 0	3.6 V to 5.5 V		1.5	7	
				2.3 V to 3.6 V		1	3.2	
				1.65 V to 2.3 V		0.5	1.7	
ΔI_{CCI}	Additional current in standby mode	SCL, SDA, $\overline{RESET}$	One input at V_{CCI} – 0.6 V, Other inputs at V_{CCI} or GND	1.65 V to 5.5 V			25	µA
ΔI_{CCP}		P-port, ADDR	One input at V_{CCP} – 0.6 V, Other inputs at V_{CCP} or GND	1.65 V to 5.5 V			80	µA
C_i	SCL		V_I = V_{CCI} or GND	1.65 V to 5.5 V		6	7	pF
C_{io}	SDA		V_{IO} = V_{CCI} or GND	1.65 V to 5.5 V		7	8	pF
	P-port		V_{IO} = V_{CCP} or GND			7.5	8.5	

(1) All typical values are at nominal supply voltage (1.8-V, 2.5-V, 3.3-V, or 5-V V_{CC}) and T_A = 25°C.
(2) When power (from 0 V) is applied to V_{CCP}, an internal power-on reset holds the TCA6408A in a reset condition until V_{CCP} has reached V_{POR}. At that time, the reset condition is released, and the TCA6408A registers and I^2C/SMBus state machine initialize to their default states. After that, V_{CCP} must be lowered to below 0.2 V and back up to the operating voltage for a power-reset cycle.

6.6 I²C Interface Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see 图 7-1)

		STANDARD MODE I²C BUS		FAST MODE I²C BUS		UNIT
		MIN	MAX	MIN	MAX	
f_{scl}	I²C clock frequency	0	100	0	400	kHz
t_{sch}	I²C clock high time	4		0.6		μs
t_{scl}	I²C clock low time	4.7		1.3		μs
t_{sp}	I²C spike time	0	50	0	50	ns
t_{sds}	I²C serial data setup time	250		100		ns
t_{sdh}	I²C serial data hold time	0		0		ns
t_{icr}	I²C input rise time		1000	20 + 0.1C_b	300	ns
t_{icf}	I²C input fall time		300	20 + 0.1C_b	300	ns
t_{ocf}	I²C output fall time, 10-pF to 400-pF bus		300	20 + 0.1C_b	300	μs
t_{buf}	I²C bus free time between Stop and Start	4.7		1.3		μs
t_{sts}	I²C Start or repeater Start condition setup time	4.7		0.6		μs
t_{sth}	I²C Start or repeater Start condition hold time	4		0.6		μs
t_{sps}	I²C Stop condition setup time	4		0.6		μs
$t_{vd(data)}$	Valid data time, SCL low to SDA output valid		1		1	μs
$t_{vd(ack)}$	Valid data time of ACK condition, ACK signal from SCL low to SDA (out) low		1		1	μs

6.7 Reset Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see 图 7-4)

		STANDARD MODE I²C BUS		FAST MODE I²C BUS		UNIT
		MIN	MAX	MIN	MAX	
t_W	Reset pulse duration	4		4		ns
t_{REC}	Reset recovery time	0		0		ns
t_{RESET}	Time to reset	600		600		ns

6.8 Switching Characteristics

over recommended operating free-air temperature range, $C_L \leqslant 100$ pF (unless otherwise noted) (see 图 7-1)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	STANDARD MODE I^2C BUS		FAST MODE I^2C BUS		UNIT
				MIN	MAX	MIN	MAX	
t_{iv}	Interrupt valid time	P-Port	$\overline{INT}$		4		4	μs
t_{ir}	Interrupt reset delay time	SCL	$\overline{INT}$		4		4	μs
t_{pv}	Output data valid	SCL	P7 – P0		400		400	ns
t_{ps}	Input data setup time	P-Port	SCL	0		0		ns
t_{ph}	Input data hold time	P-Port	SCL	300		300		ns

6.9 Typical Characteristics

T_A = 25°C (unless otherwise noted)

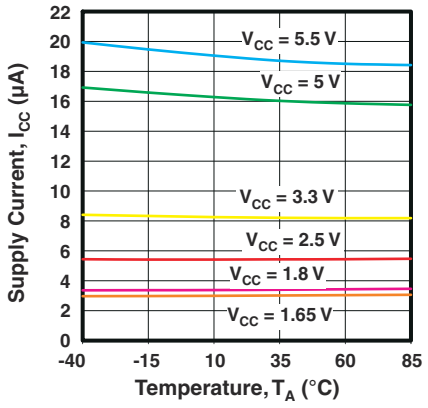


图 6-1. Supply Current vs Temperature

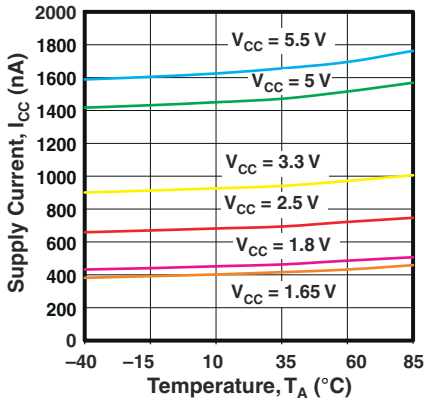


图 6-2. Standby Supply Current vs Temperature

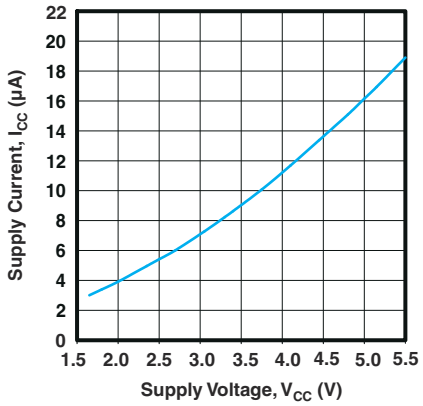


图 6-3. Supply Current vs Supply Voltage

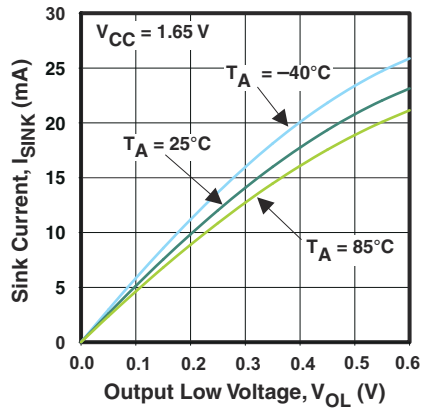


图 6-4. I/O Sink Current vs Output Low Voltage

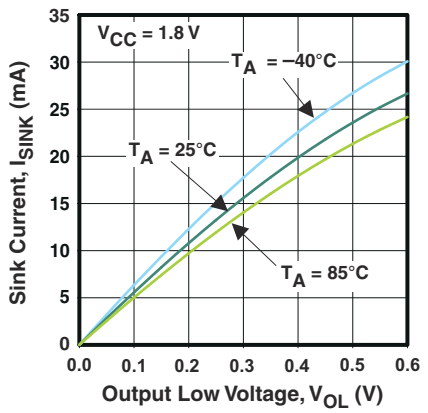


图 6-5. I/O Sink Current vs Output Low Voltage

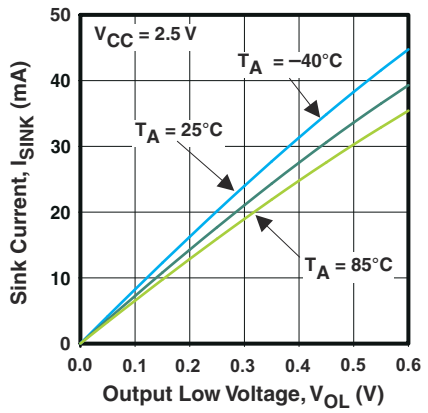


图 6-6. I/O Sink Current vs Output Low Voltage

6.9 Typical Characteristics (continued)

T_A = 25°C (unless otherwise noted)

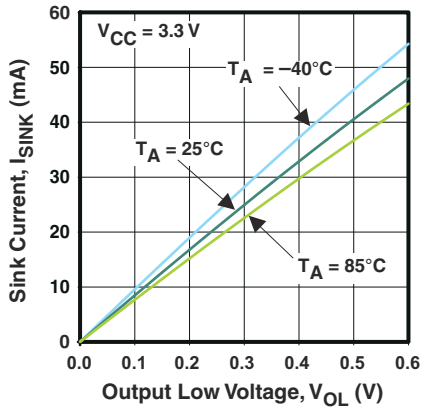


图 6-7. I/O Sink Current vs Output Low Voltage

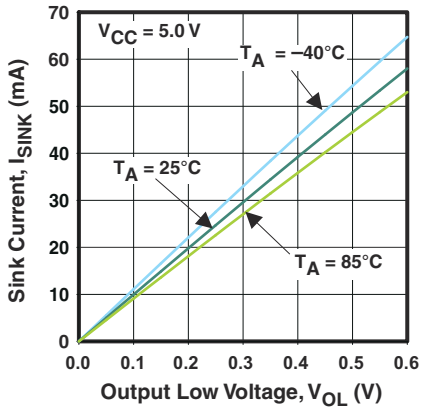


图 6-8. I/O Sink Current vs Output Low Voltage

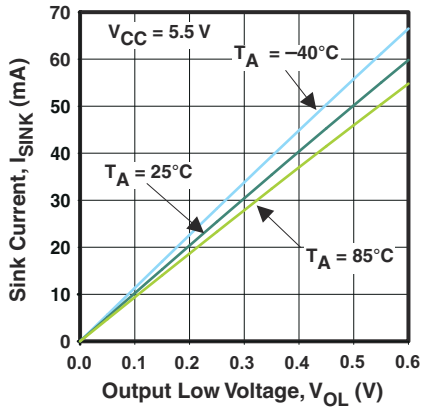


图 6-9. I/O Sink Current vs Output Low Voltage

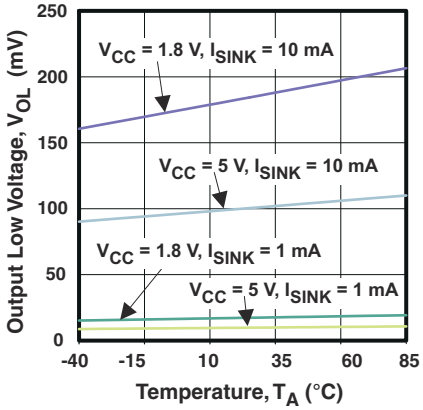


图 6-10. I/O Low Voltage vs Temperature

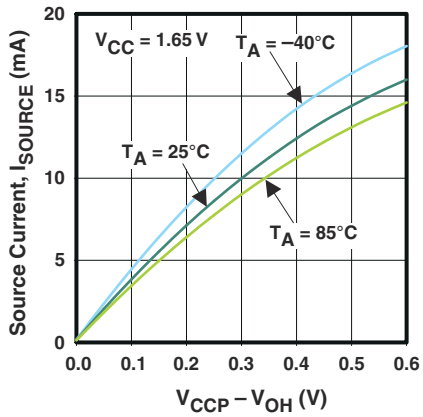


图 6-11. I/O Source Current vs Output High Voltage

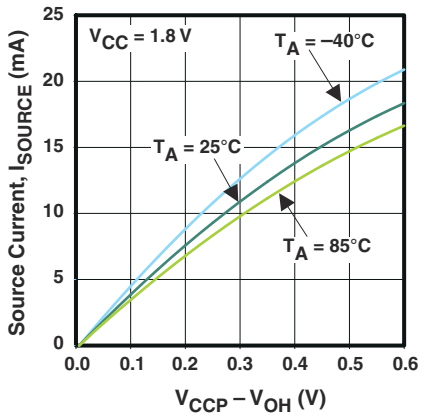


图 6-12. I/O Source Current vs Output High Voltage

6.9 Typical Characteristics (continued)

T_A = 25°C (unless otherwise noted)

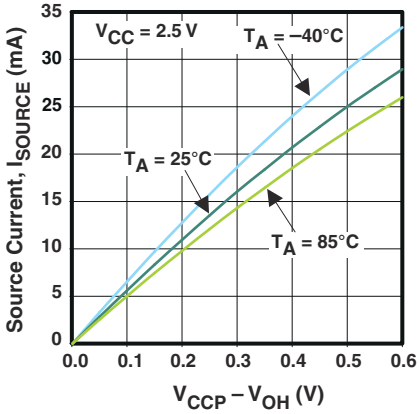


图 6-13. I/O Source Current vs Output High Voltage

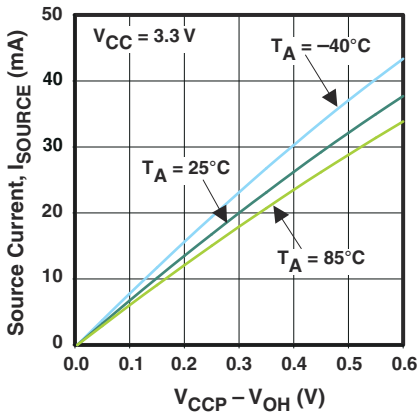


图 6-14. I/O Source Current vs Output High Voltage

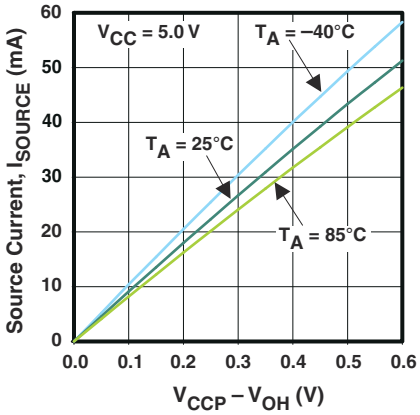


图 6-15. I/O Source Current vs Output High Voltage

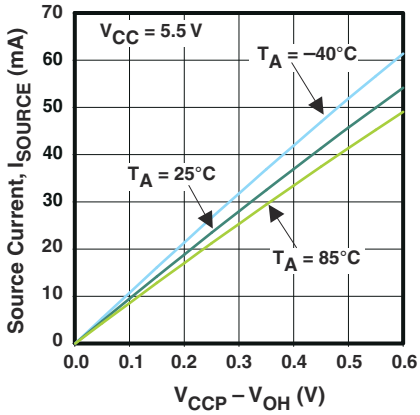


图 6-16. I/O Source Current vs Output High Voltage

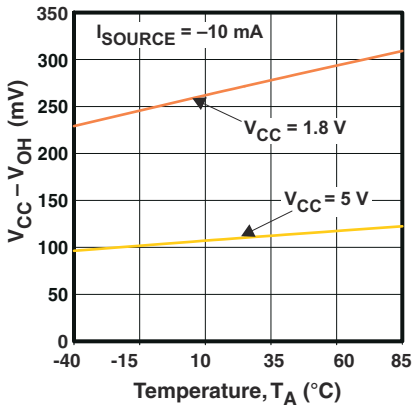
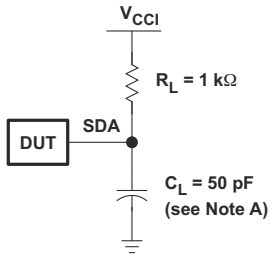
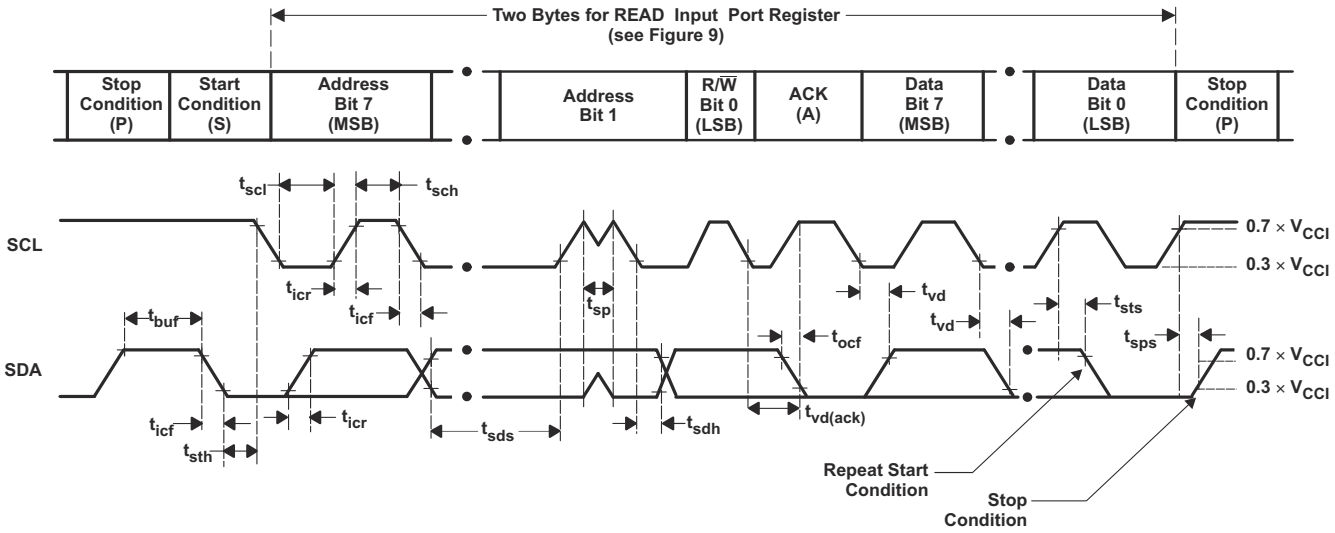


图 6-17. I/O High Voltage vs Temperature

7 Parameter Measurement Information



SDA LOAD CONFIGURATION



VOLTAGE WAVEFORMS

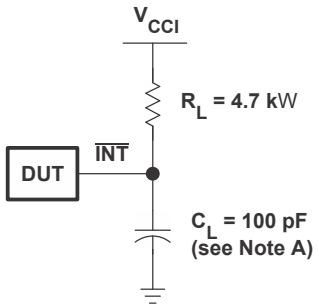
BYTE	DESCRIPTION
1	I^2C address
2	Input register port data

A. C_L includes probe and jig capacitance. tocf is measured with C_L of 10 pF or 400 pF.

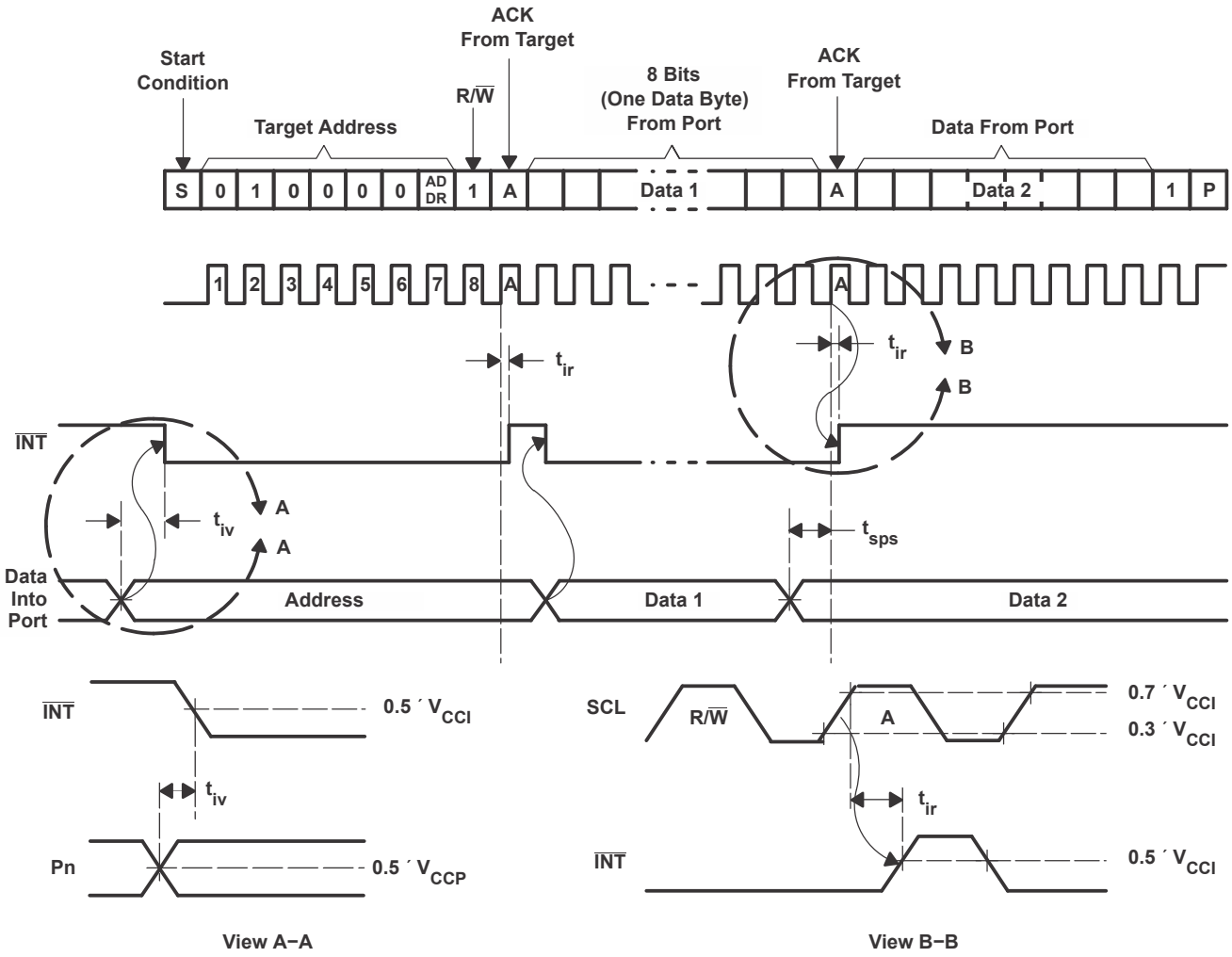
B. All inputs are supplied by generators having the following characteristics: PRR ⩽ 10 MHz, Z_O = 50 Ω, t_r/t_f ⩽ 30 ns.

C. All parameters and waveforms are not applicable to all devices.

图 7-1. I^2C Interface Load Circuit and Voltage Waveforms

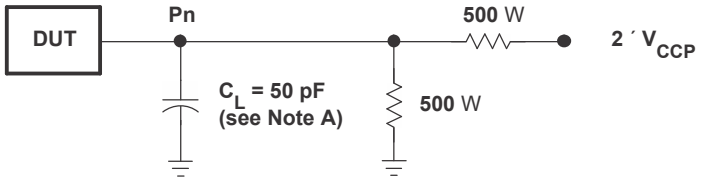


INTERRUPT LOAD CONFIGURATION

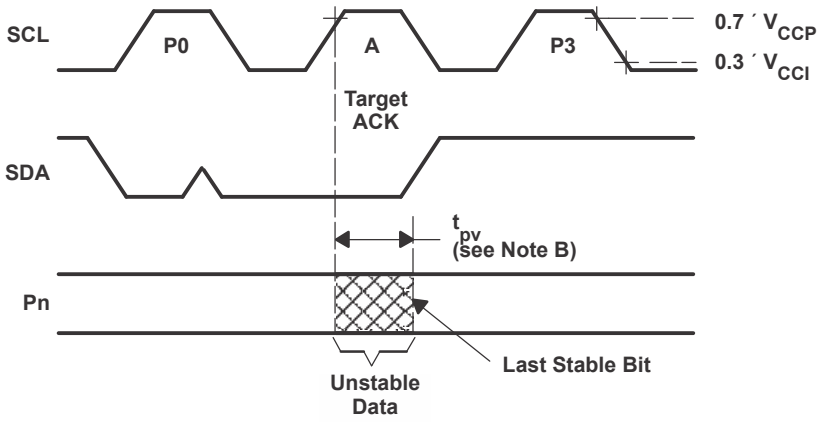


A. C_L includes probe and jig capacitance.
B. All inputs are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f ≤ 30 ns.
C. All parameters and waveforms are not applicable to all devices.

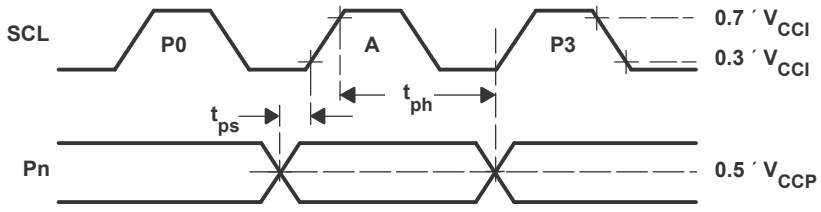
图 7-2. Interrupt Load Circuit And Voltage Waveforms



P-PORT LOAD CONFIGURATION



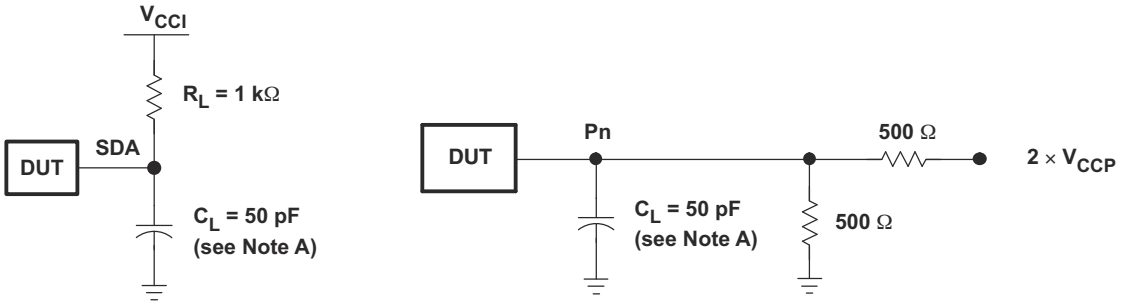
WRITE MODE (R/$\overline{W}$ = 0)



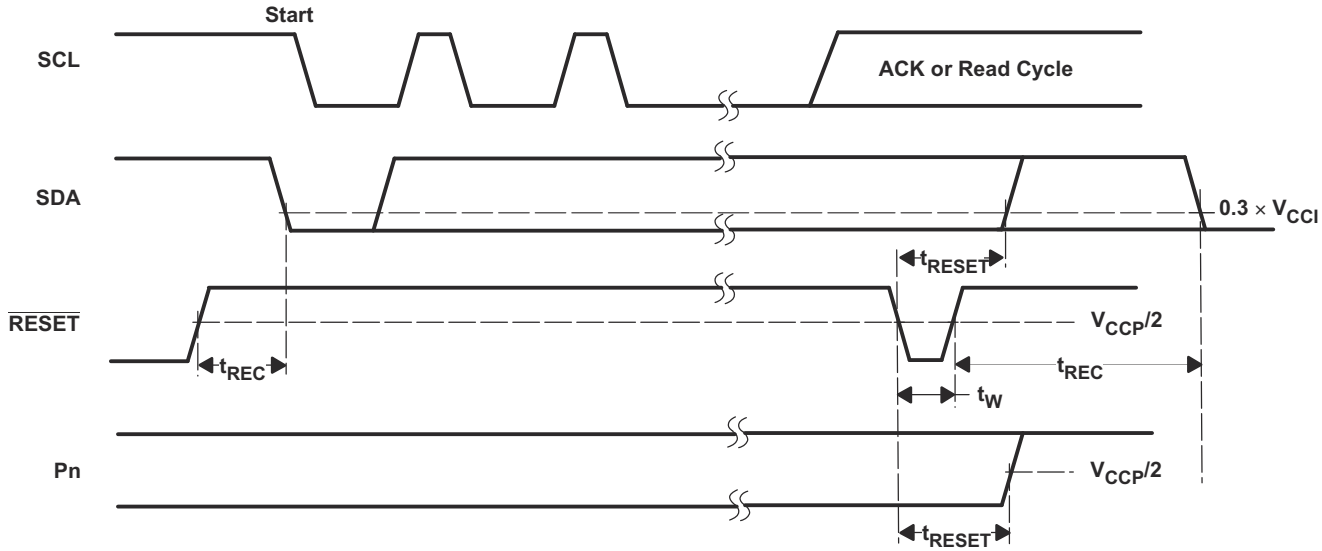
READ MODE (R/$\overline{W}$ = 1)

A. C_L includes probe and jig capacitance.
B. t_{pv} is measured from 0.7 × V_{CC} on SCL to 50% I/O (Pn) output.
C. All inputs are supplied by generators having the following characteristics: PRR ⩽ 10 MHz, Z_O = 50 Ω, t_r/t_f ⩽ 30 ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. All parameters and waveforms are not applicable to all devices.

图 7-3. P-Port Load Circuit And Timing Waveforms



SDA LOAD CONFIGURATION　　P-PORT LOAD CONFIGURATION



A. C_L includes probe and jig capacitance.
B. All inputs are supplied by generators having the following characteristics: PRR ⩽ 10 MHz, Z_O = 50 Ω, t_r/t_f ⩽ 30 ns.
C. The outputs are measured one at a time, with one transition per measurement.
D. I/Os are configured as inputs.
E. All parameters and waveforms are not applicable to all devices.

图 7-4. Reset Load Circuits And Voltage Waveforms

8 Detailed Description

8.1 Overview

The bidirectional voltage-level translation in the TCA6408A is provided through V_{CCI}. V_{CCI} should be connected to the V_{CC} of the external SCL/SDA lines. This indicates the V_{CC} level of the I^2C bus to the TCA6408A. The voltage level on the P-port of the TCA6408A is determined by V_{CCP}.

The TCA6408A consists of one 8-bit Configuration (input or output selection), Input, Output, and Polarity Inversion (active high) Register. At power on, the I/Os are configured as inputs. However, the system controller can enable the I/Os as either inputs or outputs by writing to the I/O configuration bits. The data for each input or output is kept in the corresponding Input or Output Register. The polarity of the Input Port Register can be inverted with the Polarity Inversion Register. All registers can be read by the system controller.

The system controller can reset the TCA6408A in the event of a timeout or other improper operation by asserting a low in the $\overline{\text{RESET}}$ input. The power-on reset puts the registers in their default state and initializes the I^2C/SMBus state machine. The $\overline{\text{RESET}}$ pin causes the same reset/initialization to occur without depowering the part.

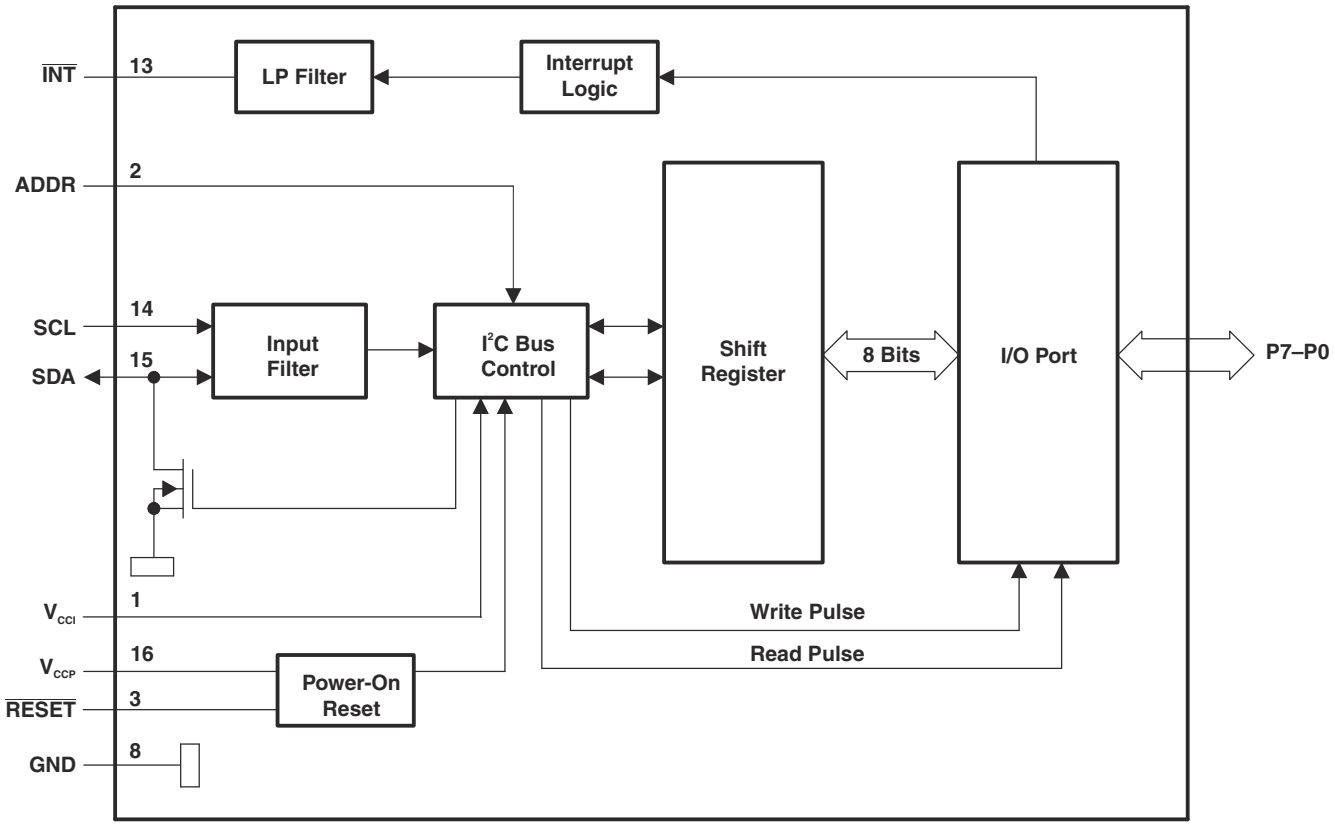
The TCA6408A open-drain interrupt ($\overline{\text{INT}}$) output is activated when any input state differs from its corresponding Input Port Register state and is used to indicate to the system controller that an input state has changed.

$\overline{\text{INT}}$ can be connected to the interrupt input of a microcontroller. By sending an interrupt signal on this line, the remote I/O can inform the microcontroller if there is incoming data on its ports without having to communicate via the I^2C bus. Thus, the TCA6408A can remain a simple target device.

The device P-port outputs have high-current sink capabilities for directly driving LEDs while consuming low device current.

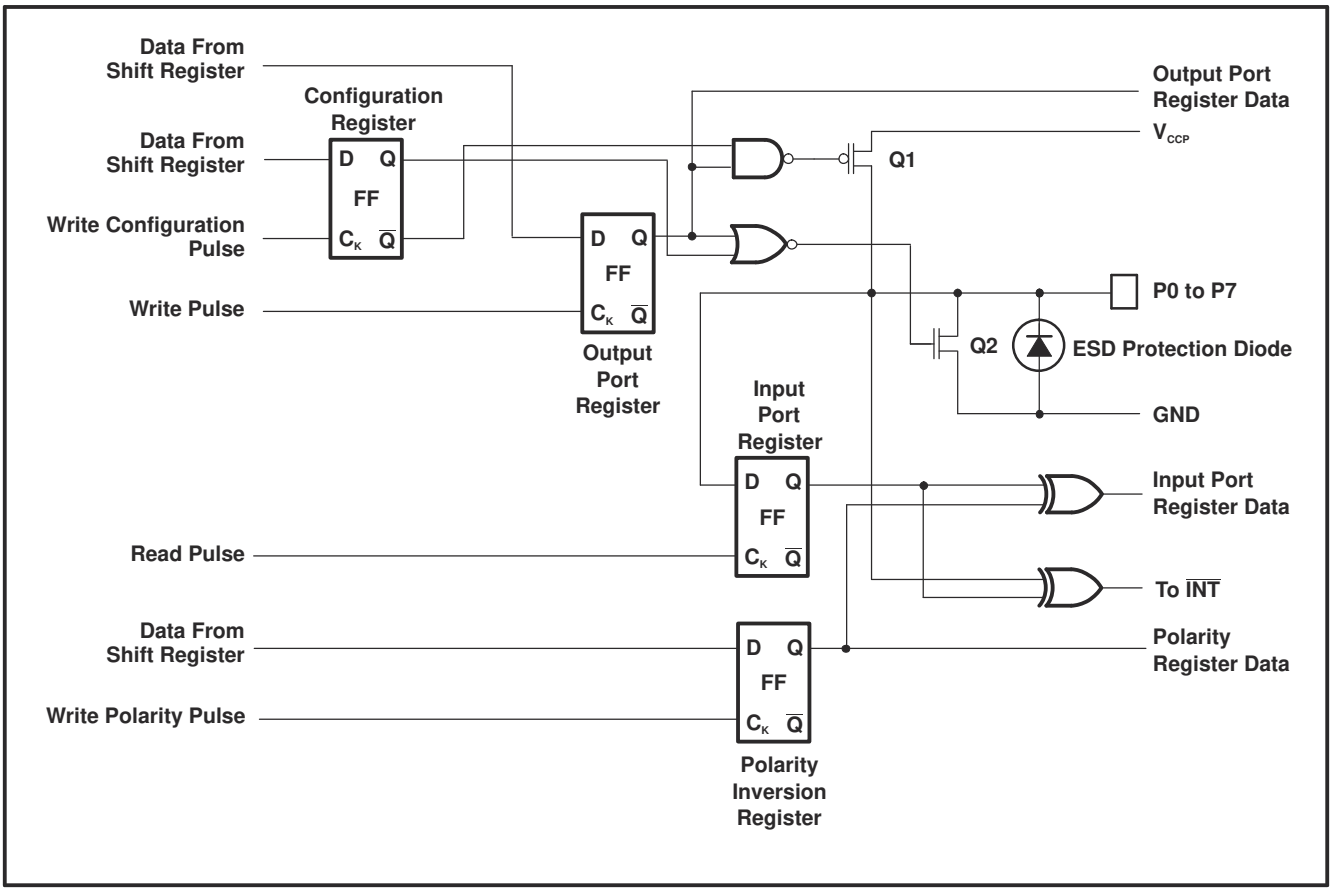
One hardware pin (ADDR) can be used to program and vary the fixed I^2C address and allow up to two devices to share the same I^2C bus or SMBus.

8.2 Functional Block Diagrams



A. All pin numbers shown are for the PW package.
B. All I/Os are set to inputs at reset.

图 8-1. Logic Diagram (Positive Logic)



A. On power up or reset, all registers return to default values.

图 8-2. Simplified Schematic of P0 to P7

8.3 Feature Description

8.3.1 Voltage Translation

表 8-1 shows some common supply voltage options for voltage translation between the I^2C bus and the P-ports of the TCA6408A.

表 8-1. Voltage Translation

V_{CCI} (SCL AND SDA OF I^2C CONTROLLER) (V)	V_{CCP} (P-PORT) (V)
1.8	1.8
1.8	2.5
1.8	3.3
1.8	5
2.5	1.8
2.5	2.5
2.5	3.3
2.5	5
3.3	1.8
3.3	2.5
3.3	3.3
3.3	5
5	1.8
5	2.5
5	3.3
5	5

8.3.2 I/O Port

When an I/O is configured as an input, FETs Q1 and Q2 are off, which creates a high-impedance input. The input voltage may be raised above V_{CC} to a maximum of 5.5 V.

If the I/O is configured as an output, Q1 or Q2 is enabled, depending on the state of the output port register. In this case, there are low-impedance paths between the I/O pin and either V_{CC} or GND. The external voltage applied to this I/O pin should not exceed the recommended levels for proper operation.

8.3.3 Interrupt Output ($\overline{INT}$)

An interrupt is generated by any rising or falling edge of the port inputs in the input mode. After time t_{iv}, the signal $\overline{INT}$ is valid. Resetting the interrupt circuit is achieved when data on the port is changed to the original setting or when data is read from the port that generated the interrupt. Resetting occurs in the read mode at the acknowledge (ACK) or not acknowledge (NACK) bit after the rising edge of the SCL signal. Interrupts that occur during the ACK or NACK clock pulse can be lost (or be very short) due to the resetting of the interrupt during this pulse. Each change of the I/Os after resetting is detected and is transmitted as $\overline{INT}$.

Reading from or writing to another device does not affect the interrupt circuit, and a pin configured as an output cannot cause an interrupt. Changing an I/O from an output to an input may cause a false interrupt to occur if the state of the pin does not match the contents of the Input Port register.

The $\overline{INT}$ output has an open-drain structure and requires pull-up resistor to V_{CCP} or V_{CCI}, depending on the application. $\overline{INT}$ should be connected to the voltage source of the device that requires the interrupt information.

8.3.4 Reset Input ($\overline{RESET}$)

The $\overline{RESET}$ input can be asserted to initialize the system while keeping the V_{CCP} at its operating level. A reset can be accomplished by holding the $\overline{RESET}$ pin low for a minimum of t_W. The TCA6408A registers and I^2C/

SMBus state machine are changed to their default state once $\overline{\text{RESET}}$ is low (0). When $\overline{\text{RESET}}$ is high (1), the I/O levels at the P-port can be changed externally or through the controller. This input requires a pull-up resistor to V_{CCI}, if no active connection is used.

8.4 Device Functional Modes

8.4.1 Power-On Reset (POR)

When power (from 0 V) is applied to V_{CCP}, an internal power-on reset holds the TCA6408A in a reset condition until V_{CCP} has reached V_{POR}. At that time, the reset condition is released, and the TCA6408A registers and I^2C/SMBus state machine initialize to their default states. After that, V_{CCP} must be lowered to below V_{PORF} and back up to the operating voltage for a power-reset cycle.

8.4.2 Powered-Up

When power has been applied to both V_{CCP} and V_{CCI} and a POR has taken place, the device is in a functioning mode. The device will always be ready to receive new requests via the I^2C bus.

8.5 Programming

8.5.1 I^2C Interface

The TCA6408A has a standard bidirectional I^2C interface that is controlled by a controller device in order to be configured or read the status of this device. Each target on the I^2C bus has a specific device address to differentiate between other target devices that are on the same I^2C bus. Many target devices will require configuration upon startup to set the behavior of the device. This is typically done when the controller accesses internal register maps of the target, which have unique register addresses. A device can have one or multiple registers where data is stored, written, or read.

The physical I^2C interface consists of the serial clock (SCL) and serial data (SDA) lines. Both SDA and SCL lines must be connected to V_{CC} through a pull-up resistor. The size of the pull-up resistor is determined by the amount of capacitance on the I^2C lines. (For further details, refer to *I^2C Pull-up Resistor Calculation* (SLVA689).) Data transfer may be initiated only when the bus is idle. A bus is considered idle if both SDA and SCL lines are high after a STOP condition.

The following is the general procedure for a controller to access a target device:

1. If a controller wants to send data to a target:
   - Controller-transmitter sends a START condition and addresses the target-receiver.
   - Controller-transmitter sends data to target-receiver.
   - Controller-transmitter terminates the transfer with a STOP condition.
2. If a controller wants to receive or read data from a target:
   - Controller-receiver sends a START condition and addresses the target-transmitter.
   - Controller-receiver sends the requested register to read to target-transmitter.
   - Controller-receiver receives data from the target-transmitter.
   - Controller-receiver terminates the transfer with a STOP condition.

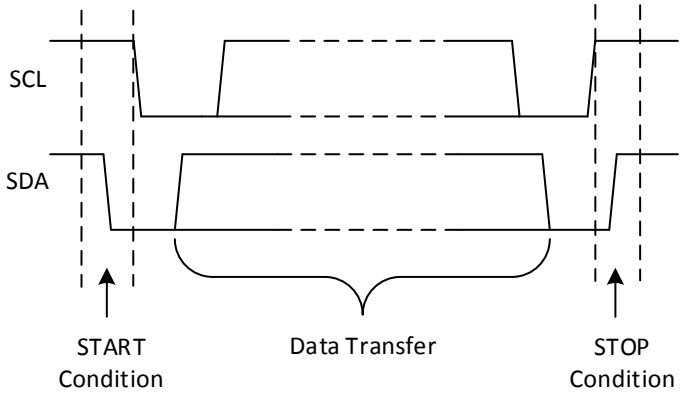


图 8-3. Definition of Start and Stop Conditions

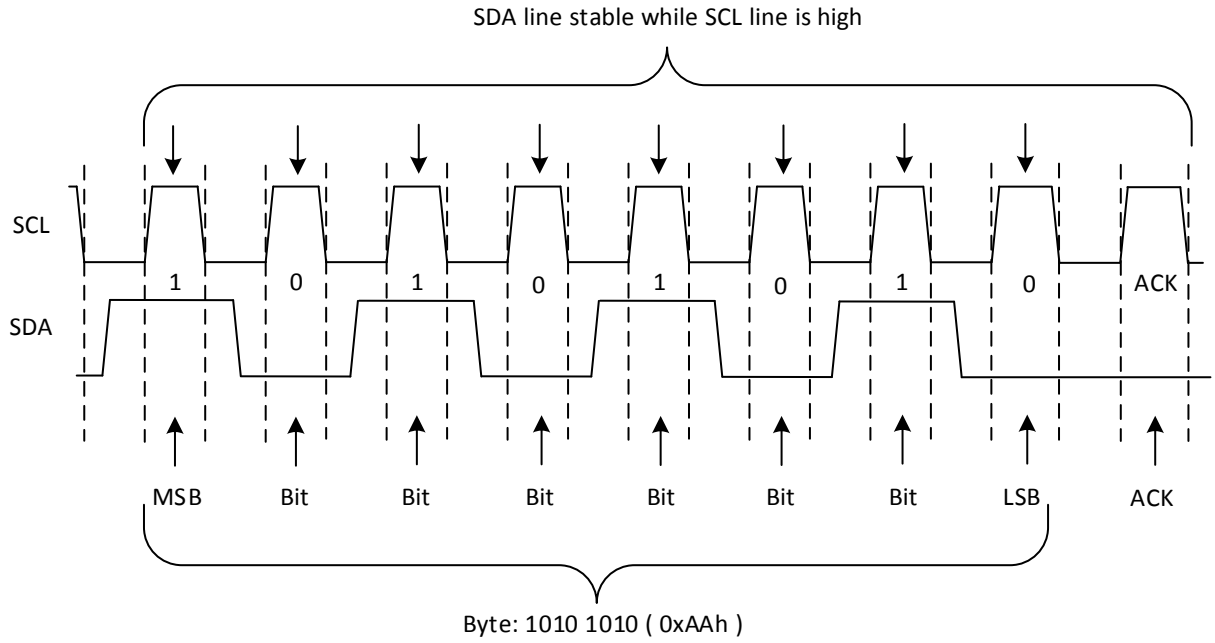


图 8-4. Bit Transfer

表 8-2. Interface Definition

BYTE	BIT							
	7 (MSB)	6	5	4	3	2	1	0 (LSB)
I^2C target address	L	H	L	L	L	L	ADDR	R/ $\overline{W}$
I/O data bus	P7	P6	P5	P4	P3	P2	P1	P0

8.5.2 Bus Transactions

Data must be sent to and received from the target devices, and this is accomplished by reading from or writing to registers in the target device.

Registers are locations in the memory of the target which contain information, whether it be the configuration information or some sampled data to send back to the controller. The controller must write information to these registers in order to instruct the target device to perform a task.

While it is common to have registers in I^2C targets, note that not all target devices will have registers. Some devices are simple and contain only 1 register, which may be written to directly by sending the register data immediately after the target address, instead of addressing a register. An example of a single-register device would be an 8-bit I^2C switch, which is controlled via I^2C commands. Since it has 1 bit to enable or disable a channel, there is only 1 register needed, and the controller merely writes the register data after the target address, skipping the register number.

8.5.2.1 Writes

To write on the I^2C bus, the controller will send a START condition on the bus with the address of the target, as well as the last bit (the R/ $\overline{W}$ bit) set to 0, which signifies a write. After the target sends the acknowledge bit, the controller will then send the register address of the register to which it wishes to write. The target will acknowledge again, letting the controller know it is ready. After this, the controller will start sending the register data to the target until the controller has sent all the data necessary (which is sometimes only a single byte), and the controller will terminate the transmission with a STOP condition.

图 8-5 shows an example of writing a single byte to a target register.

Controller controls SDA line

Target controls SDA line

Write to one register in a device

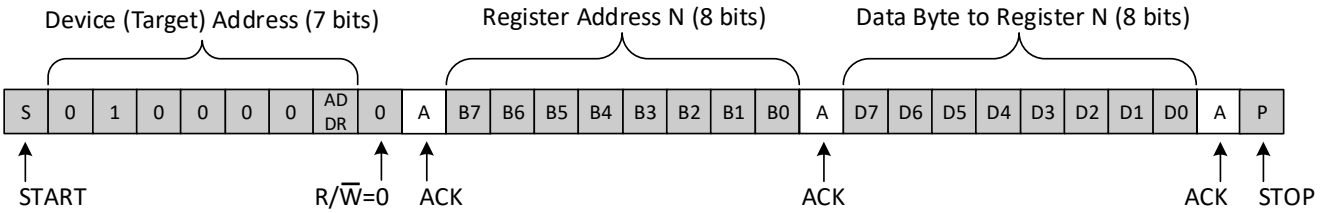


图 8-5. Write to Register

Controller controls SDA line

Target controls SDA line

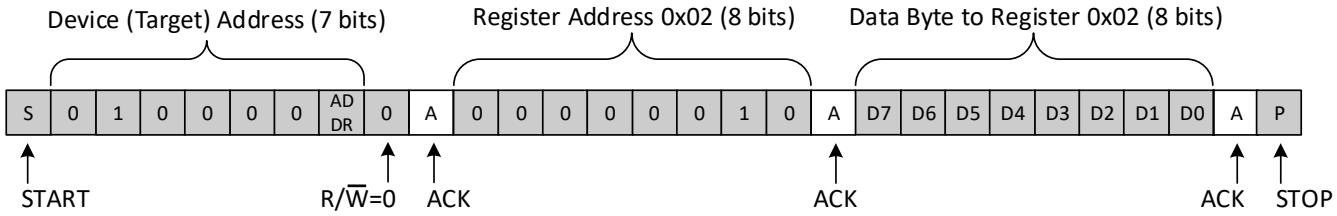


图 8-6. Write to the Polarity Inversion Register

8.5.2.2 Reads

Reading from a target is very similar to writing, but requires some additional steps. In order to read from a target, the controller must first instruct the target which register it wishes to read from. This is done by the controller starting off the transmission in a similar fashion as the write, by sending the address with the R/ $\overline{W}$ bit equal to 0 (signifying a write), followed by the register address it wishes to read from. Once the target acknowledges this register address, the controller will send a START condition again, followed by the target address with the R/ $\overline{W}$ bit set to 1 (signifying a read). This time, the target will acknowledge the read request, and the controller will release the SDA bus but will continue supplying the clock to the target. During this part of the transaction, the controller will become the controller-receiver, and the target will become the target-transmitter.

The controller will continue to send out the clock pulses, but will release the SDA line so that the target can transmit data. At the end of every byte of data, the controller will send an ACK to the target, letting the target know that it is ready for more data. Once the controller has received the number of bytes it is expecting, it will send a NACK, signaling to the target to halt communications and release the bus. The controller will follow this up with a STOP condition.

图 8-7 shows an example of reading a single byte from a target register.

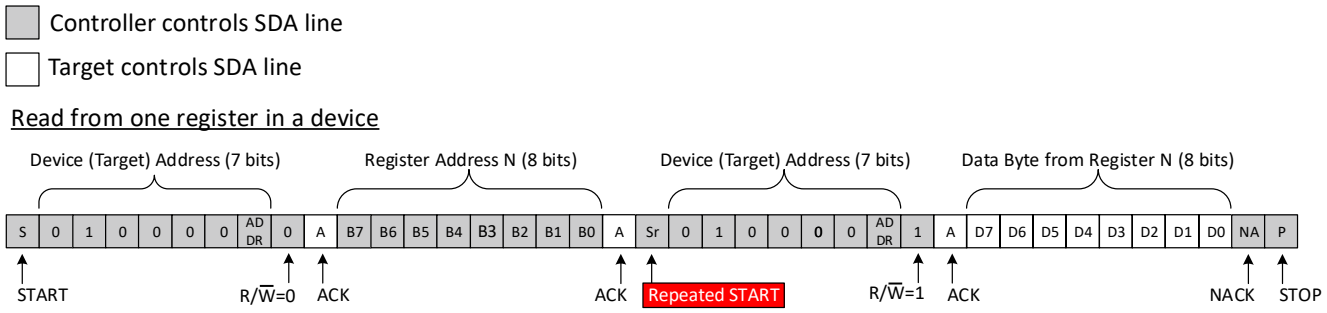
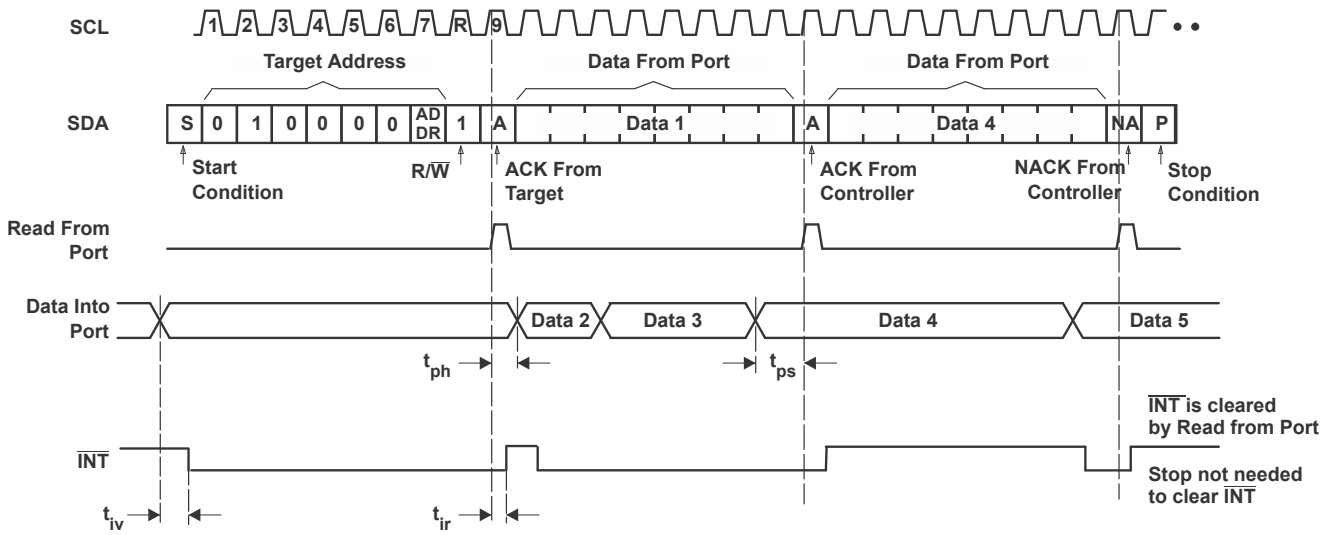


图 8-7. Read from Register



A. Transfer of data can be stopped at any time by a Stop condition. When this occurs, data present at the latest acknowledge phase is valid (output mode). It is assumed that the command byte previously has been set to 00 (read Input Port Register).

B. This figure eliminates the command byte transfer, a restart, and target address call between the initial target address call and actual data transfer from P-port (see 图 8-7).

图 8-8. Read from Input Port Register

8.6 Register Map

8.6.1 Device Address

The address of the TCA6408A is shown in 图 8-9.

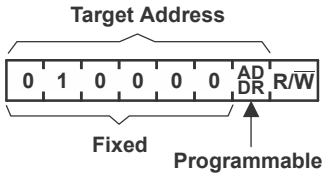


图 8-9. TCA6408A Address

表 8-3. Address Reference

ADDR	I²C BUS TARGET ADDRESS
L	32 (decimal), 20 (hexadecimal)
H	33 (decimal), 21 (hexadecimal)

The last bit of the target address defines the operation (read or write) to be performed. A high (1) selects a read operation, while a low (0) selects a write operation.

8.6.2 Control Register and Command Byte

Following the successful acknowledgment of the address byte, the bus controller sends a command byte, which is stored in the Control Register in the TCA6408A. Two bits of this data byte will state both the operation (read or write) and the internal registers (Input, Output, Polarity Inversion, or Configuration) that will be affected. This register can be written or read through the I²C bus. The command byte is sent only during a write transmission.

B7	B6	B5	B4	B3	B2	B1	B0

图 8-10. Control Register Bits

表 8-4. Command Byte

CONTROL REGISTER BITS								COMMAND BYTE (HEX)	REGISTER	PROTOCOL	POWER-UP DEFAULT
B7	B6	B5	B4	B3	B2	B1	B0				
0	0	0	0	0	0	0	0	00	Input Port	Read byte	xxxx xxxx
0	0	0	0	0	0	0	1	01	Output Port	Read/write byte	1111 1111
0	0	0	0	0	0	1	0	02	Polarity Inversion	Read/write byte	0000 0000
0	0	0	0	0	0	1	1	03	Configuration	Read/write byte	1111 1111

8.6.3 Register Descriptions

The Input Port Register (register 0) reflects the incoming logic levels of the pins, regardless of whether the pin is defined as an input or an output by the Configuration Register. They act only on read operation. Writes to this register have no effect. The default value (X) is determined by the externally applied logic level. Before a read operation, a write transmission is sent with the command byte to indicate to the I^2C device that the Input Port Register will be accessed next.

表 8-5. Register 0 (Input Port Register)

BIT	I-7	I-6	I-5	I-4	I-3	I-2	I-1	I-0
DEFAULT	X	X	X	X	X	X	X	X

The Output Port Register (register 1) shows the outgoing logic levels of the pins defined as outputs by the Configuration Register. Bit values in this register have no effect on pins defined as inputs. In turn, reads from this register reflect the value that is in the flip-flop controlling the output selection, not the actual pin value.

表 8-6. Register 1 (Output Port Register)

BIT	O-7	O-6	O-5	O-4	O-3	O-2	O-1	O-0
DEFAULT	1	1	1	1	1	1	1	1

The Polarity Inversion Register (register 2) allows polarity inversion of pins defined as inputs by the Configuration Register. If a bit in this register is set (written with 1), the polarity of the corresponding port pin is inverted. If a bit in this register is cleared (written with a 0), the original polarity of the corresponding port pin is retained.

表 8-7. Register 2 (Polarity Inversion Register)

BIT	N-7	N-6	N-5	N-4	N-3	N-2	N-1	N-0
DEFAULT	0	0	0	0	0	0	0	0

The Configuration Register (register 3) configures the direction of the I/O pins. If a bit in this register is set to 1, the corresponding port pin is enabled as an input with a high-impedance output driver. If a bit in this register is cleared to 0, the corresponding port pin is enabled as an output.

表 8-8. Register 3 (Configuration Register)

BIT	C-7	C-6	C-5	C-4	C-3	C-2	C-1	C-0
DEFAULT	1	1	1	1	1	1	1	1

9 Application and Implementation

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’s customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

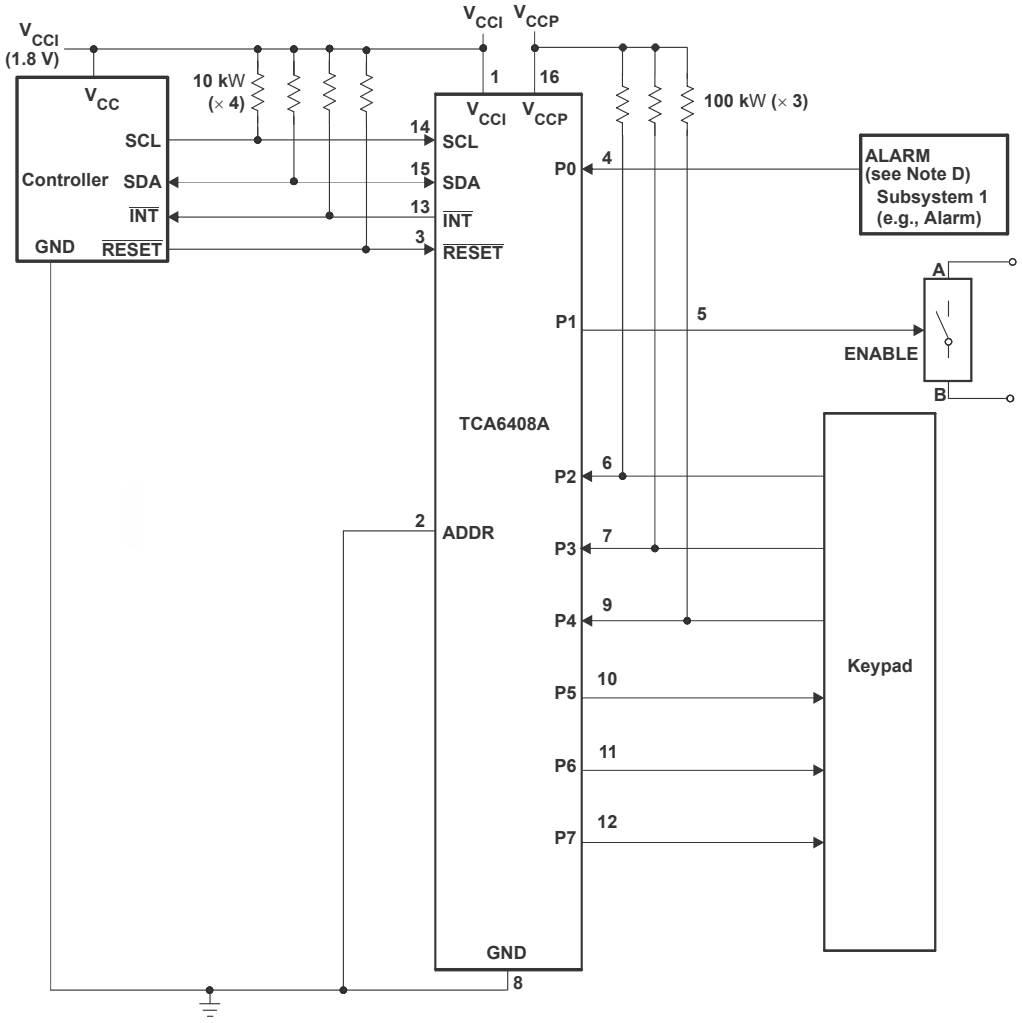
9.1 Application Information

Applications of the TCA6408A will have this device connected as a target to an I^2C controller (processor), and the I^2C bus may contain any number of other target devices. The TCA6408A will be in a remote location from the controller, placed close to the GPIOs to which the controller needs to monitor or control.

A typical application of the TCA6408A will operate with a lower voltage on the controller side (V_{CCI}), and a higher voltage on the P-port side (V_{CCP}). The P-ports can be configured as outputs connected to inputs of devices such as enable, reset, power select, the gate of a switch, and LEDs. The P-ports can also be configured as inputs to receive data from interrupts, alarms, status outputs, or push buttons.

9.2 Typical Application

图 9-1 shows an application in which the TCA6408A can be used.



A. Device address configured as 0100000 for this example.
B. P0 and P2 – P4 are configured as inputs.
C. P1 and P5 – P7 are configured as outputs.
D. Resistors are required for inputs (on P-port) that may float. If a driver to an input will never let the input float, a resistor is not needed. Outputs (in the P-port) do not need pull-up resistors.

图 9-1. Typical Application Schematic

9.2.1 Design Requirements

表 9-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
I^2C input voltage (V_{CCI})	1.8 V
P-port input/output voltage (V_{CCP})	5 V
Output current rating, P-port sinking (I_{OL})	25 mA
Output current rating, P-port sourcing (I_{OH})	10 mA
I^2C bus clock (SCL) speed	400 kHz

9.2.2 Detailed Design Procedure

The pull-up resistors, R_P, for the SCL and SDA lines need to be selected appropriately and take into consideration the total capacitance of all targets on the I^2C bus. The minimum pull-up resistance is a function of V_{CC}, $V_{OL,(max)}$, and I_{OL}:

$$R_{p(min)} = \frac{V_{CC} - V_{OL(max)}}{I_{OL}} \quad (1)$$

The maximum pull-up resistance is a function of the maximum rise time, t_r (300 ns for fast-mode operation, f_{SCL} = 400 kHz) and bus capacitance, C_b:

$$R_{p(max)} = \frac{t_r}{0.8473 \times C_b} \quad (2)$$

The maximum bus capacitance for an I^2C bus must not exceed 400 pF for standard-mode or fast-mode operation. The bus capacitance can be approximated by adding the capacitance of the TCA9538, C_i for SCL or C_{IO} for SDA, the capacitance of wires, connections, and traces, and the capacitance of additional targets on the bus.

9.2.2.1 Minimizing I_{CC} When I/O is Used to Control LEDs

When the I/Os are used to control LEDs, normally they are connected to V_{CC} through a resistor as shown in 图 9-1. The LED acts as a diode, so when the LED is off, the I/O V_{IN} is about 1.2 V less than V_{CC}. The ΔI_{CC} parameter in *节 6.5* shows how I_{CC} increases as V_{IN} becomes lower than V_{CC}. Designs that must minimize current consumption, such as battery power applications, should consider maintaining the I/O pins greater than or equal to V_{CC} when the LED is off.

图 9-2 shows a high-value resistor in parallel with the LED. 图 9-3 shows V_{CC} less than the LED supply voltage by at least 1.2 V. Both of these methods maintain the I/O V_{IN} at or above V_{CC} and prevent additional supply current consumption when the LED is off.

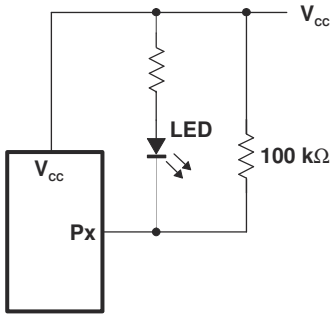


图 9-2. High-Value Resistor in Parallel With LED

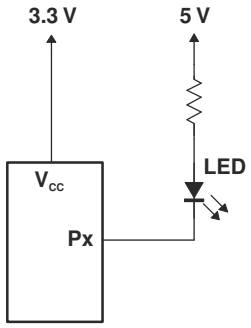
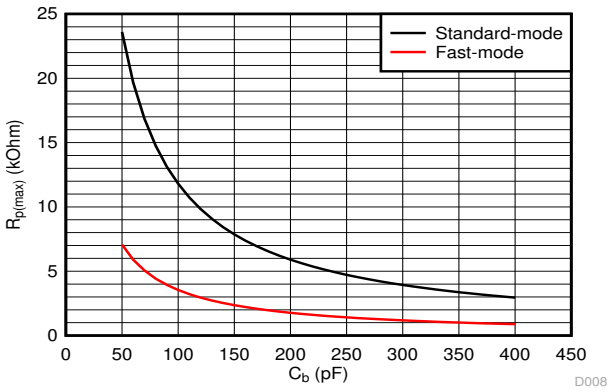


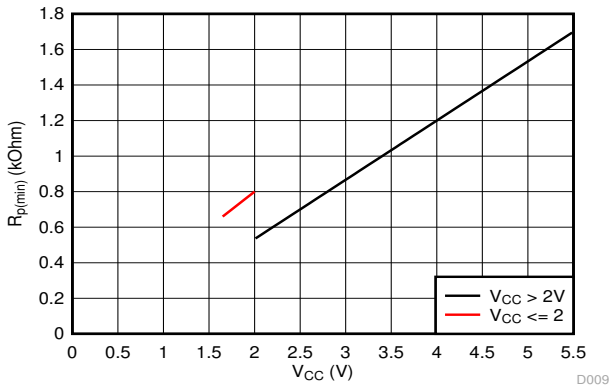
图 9-3. Device Supplied by a Low Voltage

9.2.3 Application Curves



Standard-mode: f_{SCL}= 100 kHz, t_r = 1 µs
Fast-mode: f_{SCL}= 400 kHz, t_r= 300 ns

图 9-4. Maximum Pullup Resistance ($R_{p(max)}$) vs Bus Capacitance (C_b)



V_{OL} = 0.2 × V_{CC}, I_{OL} = 2 mA when $V_{CC} \leqslant$ 2 V
V_{OL} = 0.4 V, I_{OL} = 3 mA when V_{CC} > 2 V

图 9-5. Minimum Pullup Resistance ($R_{p(min)}$) vs Pullup Reference Voltage (V_{CC})

10 Power Supply Recommendations

10.1 Power-On Reset Requirements

In the event of a glitch or data corruption, TCA6408A can be reset to its default conditions by using the power-on reset feature. Power-on reset requires that the device go through a power cycle to be completely reset. This reset also happens when the device is powered on for the first time in an application.

Ramping up the device V_{CCP} before V_{CCI} is recommended to prevent SDA from potentially being stuck LOW.

The two types of power-on reset are shown in 图 10-1 and 图 10-2.

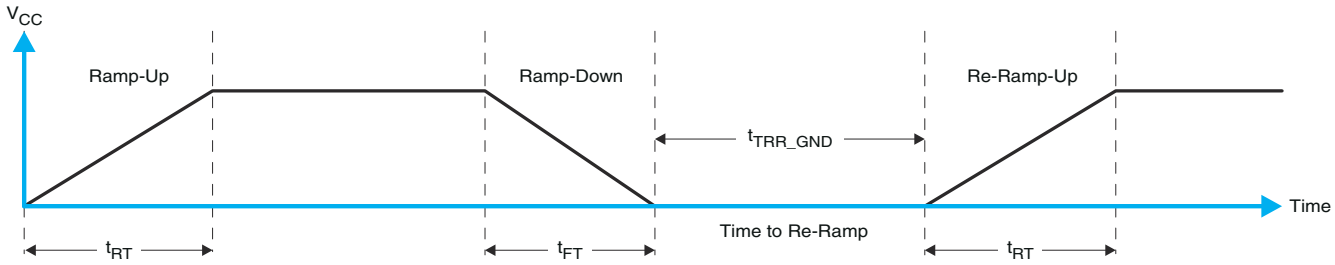


图 10-1. V_{CC} is Lowered Below 0.2 V Or 0 V and then Ramped Up to V_{CC}

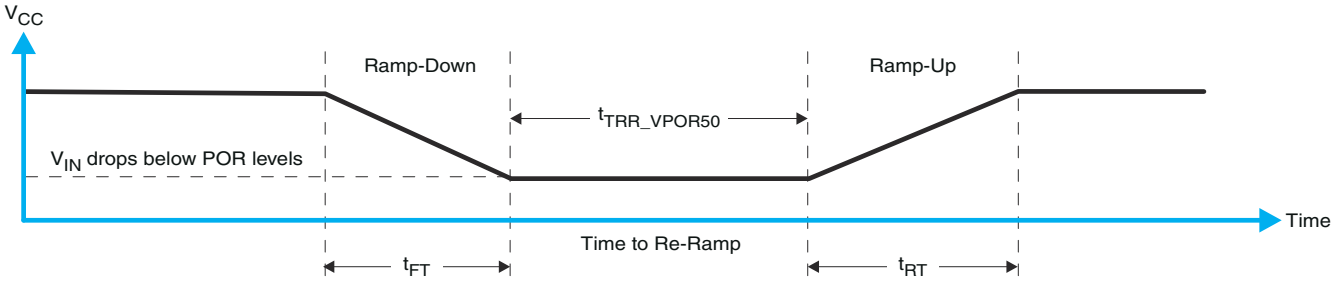


图 10-2. V_{CC} is Lowered Below the POR Threshold, then Ramped Back Up to V_{CC}

表 10-1 specifies the performance of the power-on reset feature for TCA6408A for both types of power-on reset.

表 10-1. Recommended Supply Sequencing and Ramp Rates at T_A = 25°C(1)

PARAMETER			MIN	TYP	MAX	UNIT
t_{FT}	Fall rate	See 图 10-1	0.1		2000	ms
t_{RT}	Rise rate	See 图 10-1	0.1		2000	ms
t_{RR_GND}	Time to re-ramp (when V_{CC} drops to GND)	See 图 10-1	1			µs
t_{RR_POR50}	Time to re-ramp (when V_{CC} drops to V_{POR_MIN} – 50 mV)	See 图 10-2	1			µs
V_{CC_GH}	Level that V_{CCP} can glitch down to, but not cause a functional disruption when V_{CCX_GW} = 1 µs	See 图 10-3			1.2	V
t_{GW}	Glitch width that will not cause a functional disruption when V_{CCX_GH} = 0.5 × V_{CCx}	See 图 10-3			10	µs
V_{PORF}	Voltage trip point of POR on falling V_{CC}		0.7			V
V_{PORR}	Voltage trip point of POR on rising V_{CC}				1.4	V

(1) Not tested. Specified by design.

Glitches in the power supply can also affect the power-on reset performance of this device. The glitch width (t_{GW}) and height (t_{GH}) are dependent on each other. The bypass capacitance, source impedance, and device impedance are factors that affect power-on reset performance. 图 10-3 and 表 10-1 provide more information on how to measure these specifications.

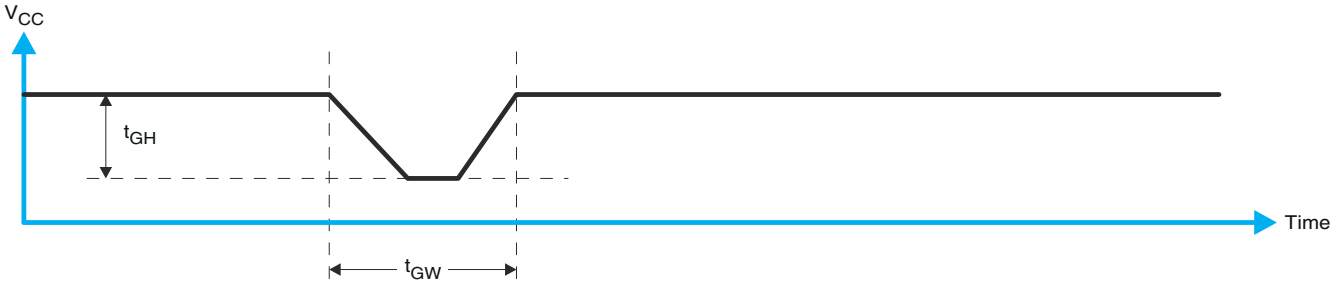


图 10-3. Glitch Width And Glitch Height

V_{POR} is critical to the power-on reset. V_{POR} is the voltage level at which the reset condition is released and all the registers and the I^2C/SMBus state machine are initialized to the default states. The value of V_{POR} differs based on the V_{CC} being lowered to or from 0. 图 10-4 and 表 10-1 provide more details on this specification.

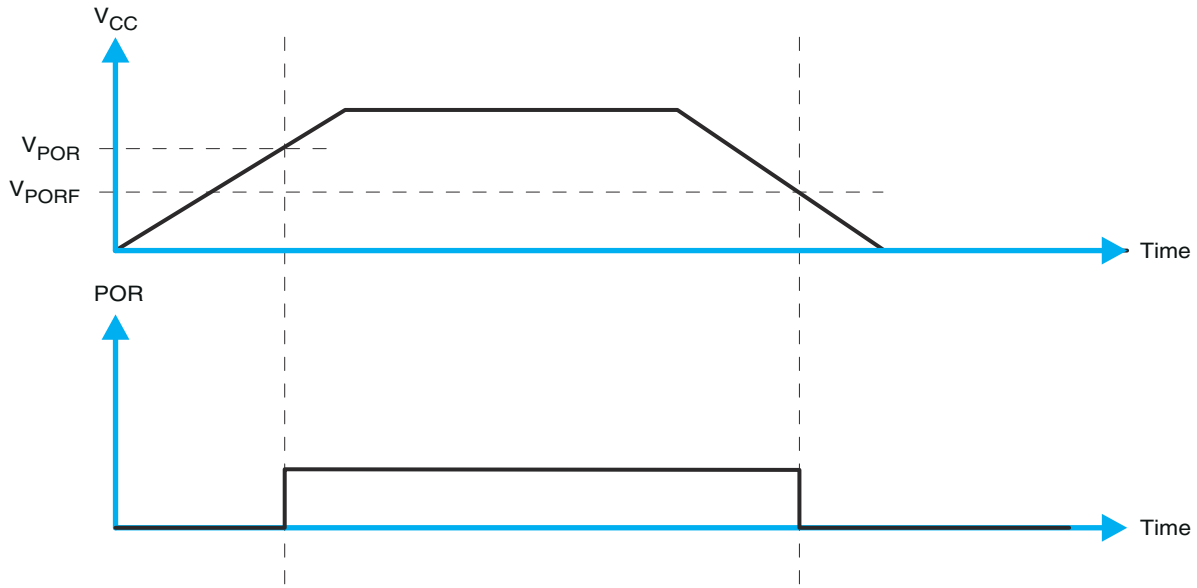


图 10-4. V_{POR}

11 Layout

11.1 Layout Guidelines

For printed circuit board (PCB) layout of the TCA6408A, common PCB layout practices should be followed, but additional concerns related to high-speed data transfer such as matched impedances and differential pairs are not a concern for I^2C signal speeds.

In all PCB layouts, it is a best practice to avoid right angles in signal traces, to fan out signal traces away from each other upon leaving the vicinity of an integrated circuit (IC), and to use thicker trace widths to carry higher amounts of current that commonly pass through power and ground traces. By-pass and de-coupling capacitors are commonly used to control the voltage on the V_{CCP} pin, using a larger capacitor to provide additional power in the event of a short power supply glitch and a smaller capacitor to filter out high-frequency ripple. These capacitors should be placed as close to the TCA6408A as possible. These best practices are shown in 节 11.2.

For the layout example provided in 节 11.2, it would be possible to fabricate a PCB with only 2 layers by using the top layer for signal routing and the bottom layer as a split plane for power (V_{CCI} and V_{CCP}) and ground (GND). However, a 4-layer board is preferable for boards with higher density signal routing. On a 4-layer PCB, it is common to route signals on the top and bottom layer, dedicate one internal layer to a ground plane, and dedicate the other internal layer to a power plane. In a board layout using planes or split planes for power and ground, vias are placed directly next to the surface mount component pad which needs to attach to V_{CCI}, V_{CCP}, or GND and the via is connected electrically to the internal layer or the other side of the board. Vias are also used when a signal trace needs to be routed to the opposite side of the board, but this technique is not demonstrated in 节 11.2.

11.2 Layout Example

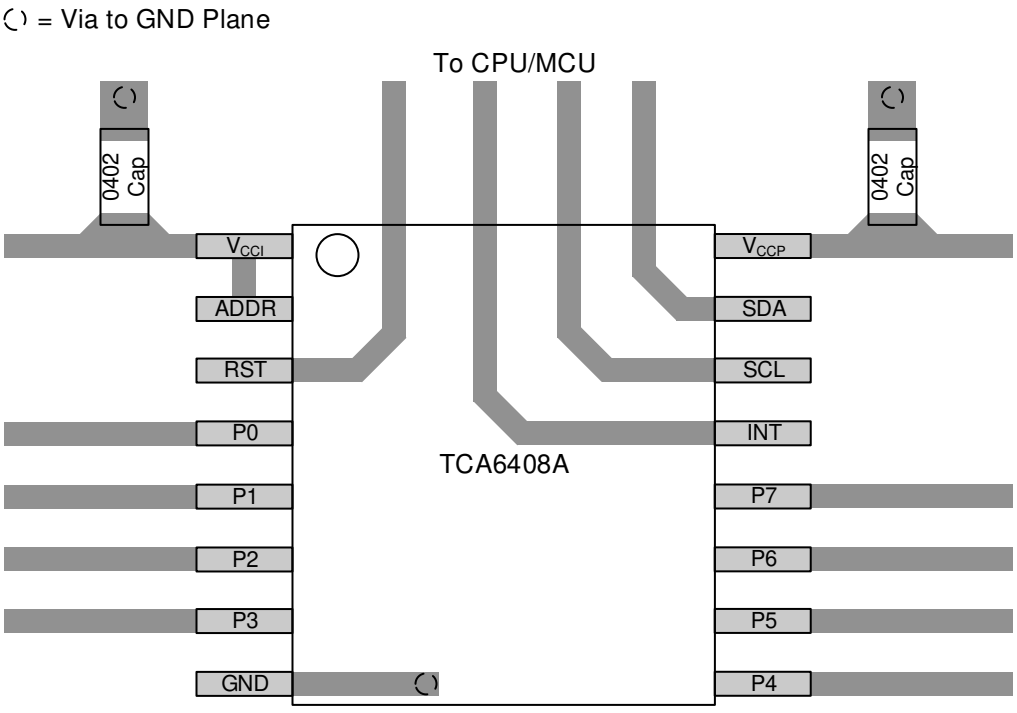


图 11-1. Example Layout (PW Package)

12 Device and Documentation Support

12.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 *订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

12.2 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

12.3 商标

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

12.4 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

12.5 术语表

TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TCA6408APWR	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PH408A
TCA6408APWR.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PH408A
TCA6408APWR.B	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PH408A
TCA6408APWRG4	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PH408A
TCA6408APWRG4.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PH408A
TCA6408APWRG4.B	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PH408A
TCA6408ARGTR	Active	Production	VQFN (RGT) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZVU
TCA6408ARGTR.A	Active	Production	VQFN (RGT) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZVU
TCA6408ARGTR.B	Active	Production	VQFN (RGT) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZVU
TCA6408ARGTRG4	Active	Production	VQFN (RGT) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZVU
TCA6408ARGTRG4.A	Active	Production	VQFN (RGT) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZVU
TCA6408ARGTRG4.B	Active	Production	VQFN (RGT) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZVU
TCA6408ARSVR	Active	Production	UQFN (RSV) | 16	3000 | LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	ZVU
TCA6408ARSVR.A	Active	Production	UQFN (RSV) | 16	3000 | LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	ZVU
TCA6408ARSVR.B	Active	Production	UQFN (RSV) | 16	3000 | LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	ZVU

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF TCA6408A :

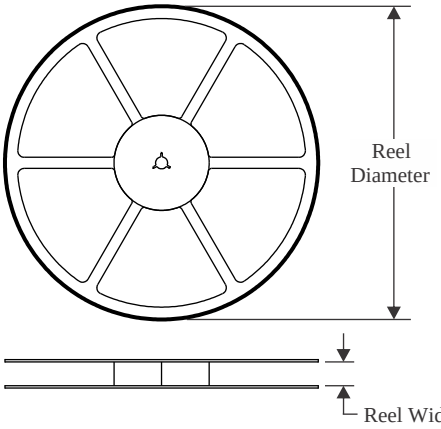
- Automotive : TCA6408A-Q1

NOTE: Qualified Version Definitions:

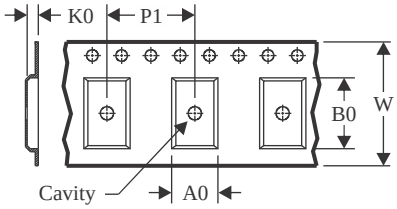
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

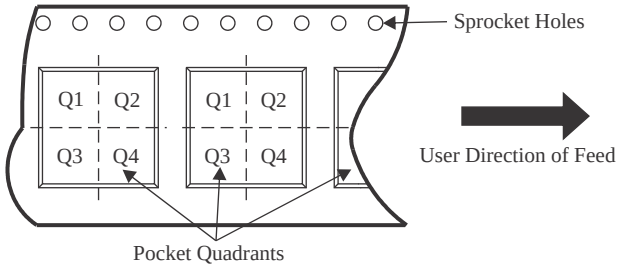


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

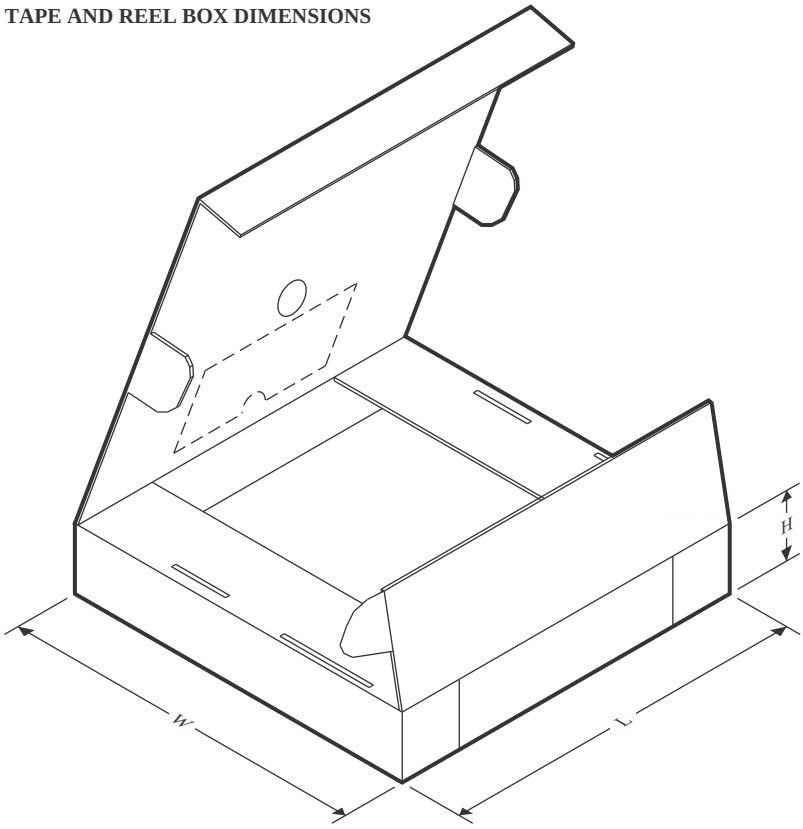
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA6408APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TCA6408APWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TCA6408ARGTR	VQFN	RGT	16	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TCA6408ARGTRG4	VQFN	RGT	16	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TCA6408ARSVR	UQFN	RSV	16	3000	177.8	12.4	2.0	2.8	0.7	4.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA6408APWR	TSSOP	PW	16	2000	353.0	353.0	32.0
TCA6408APWRG4	TSSOP	PW	16	2000	353.0	353.0	32.0
TCA6408ARGTR	VQFN	RGT	16	3000	353.0	353.0	32.0
TCA6408ARGTRG4	VQFN	RGT	16	3000	353.0	353.0	32.0
TCA6408ARSVR	UQFN	RSV	16	3000	202.0	201.0	28.0

GENERIC PACKAGE VIEW

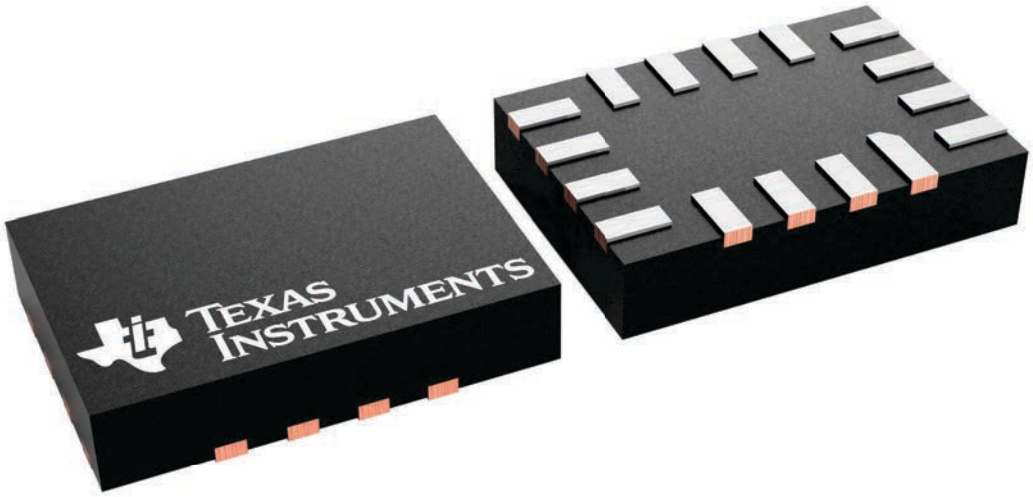
RSV 16

UQFN - 0.55 mm max height

1.8 x 2.6, 0.4 mm pitch

ULTRA THIN QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



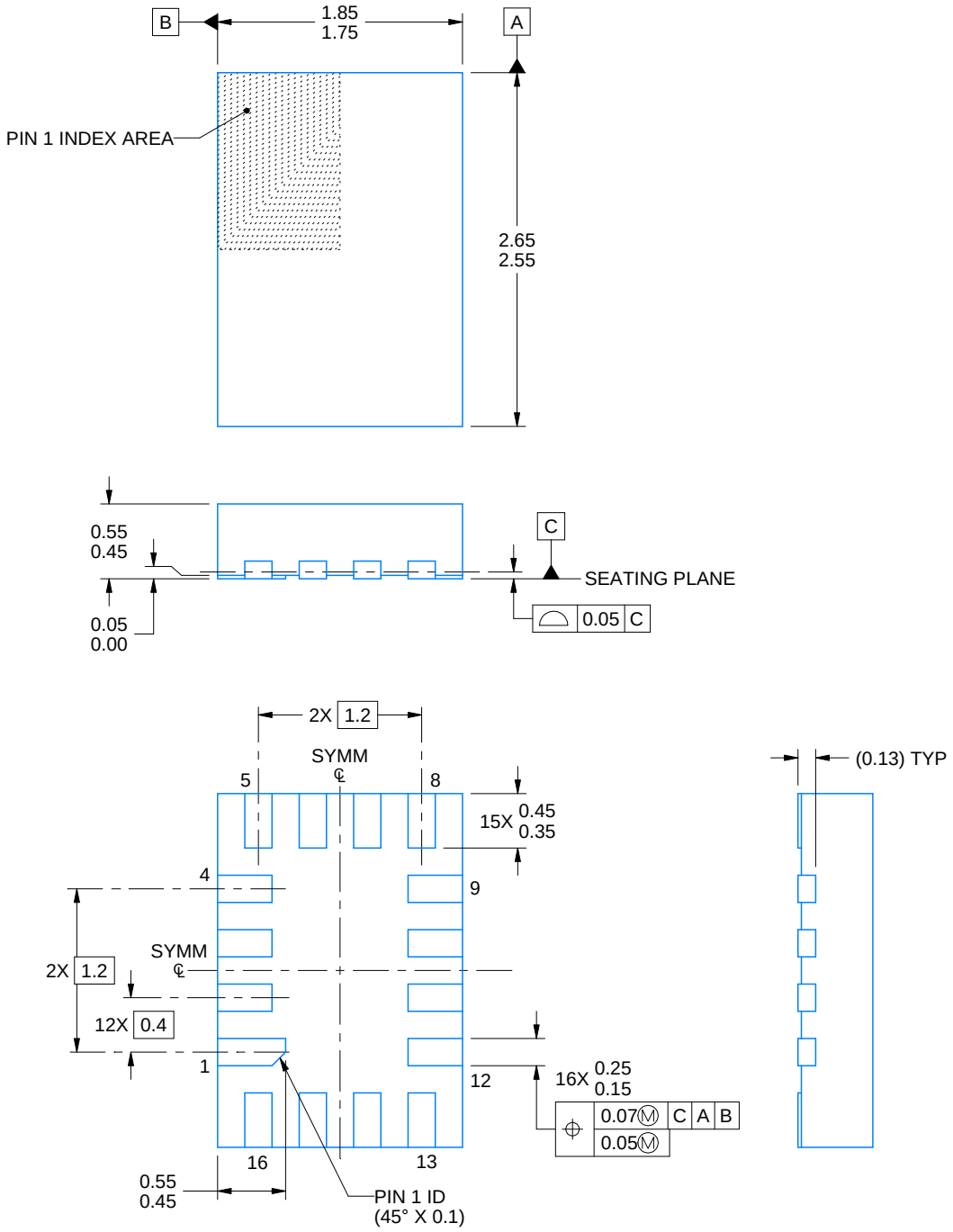
4231225/A

RSV0016A

PACKAGE OUTLINE

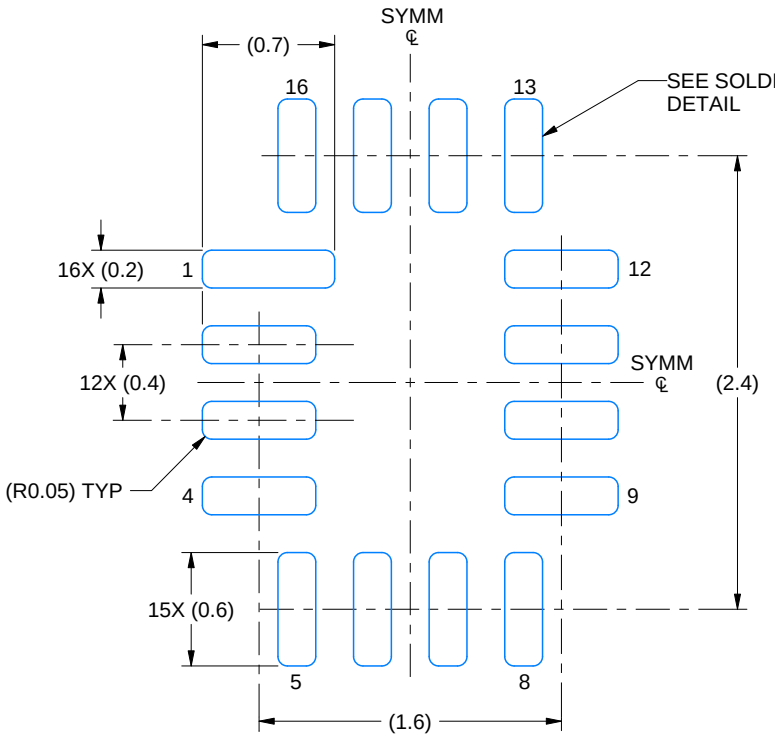
UQFN - 0.55 mm max height

ULTRA THIN QUAD FLATPACK - NO LEAD

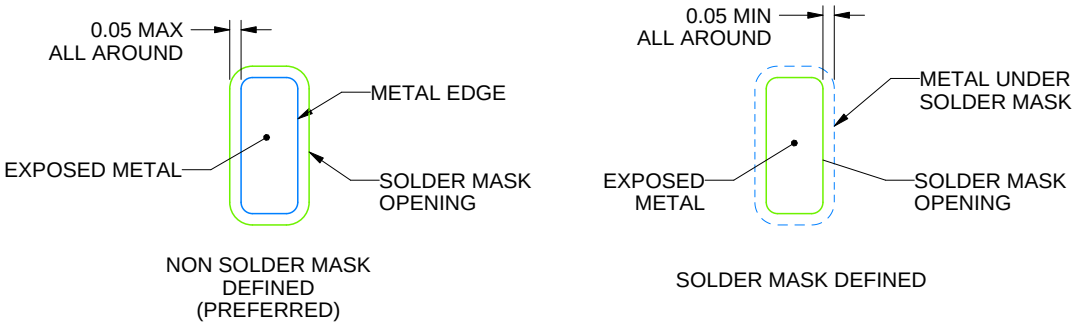


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 25X

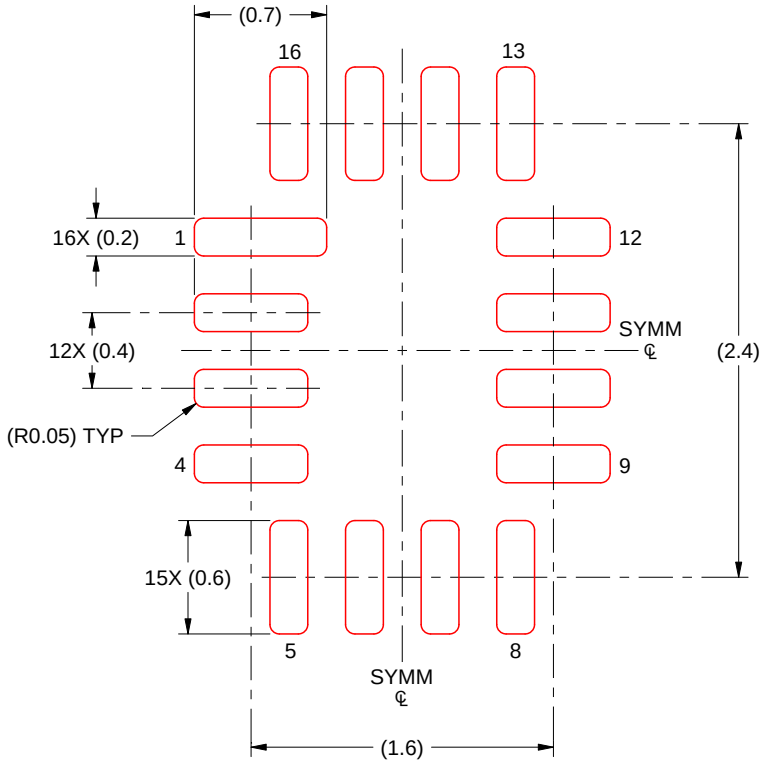


SOLDER MASK DETAILS

4220314/C 02/2020

NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 25X

4220314/C 02/2020

NOTES: (continued)

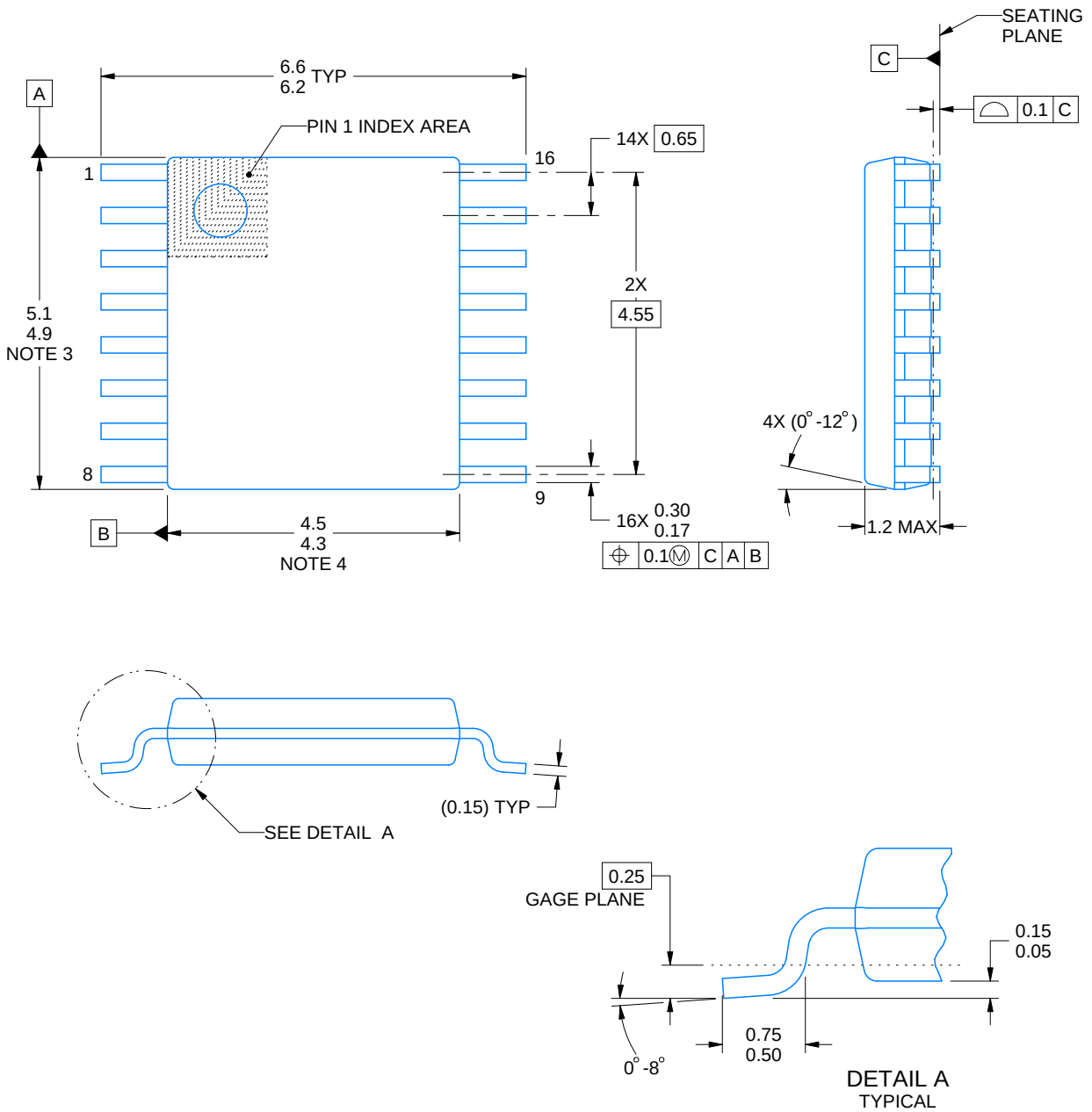
4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGE OUTLINE

PW0016A

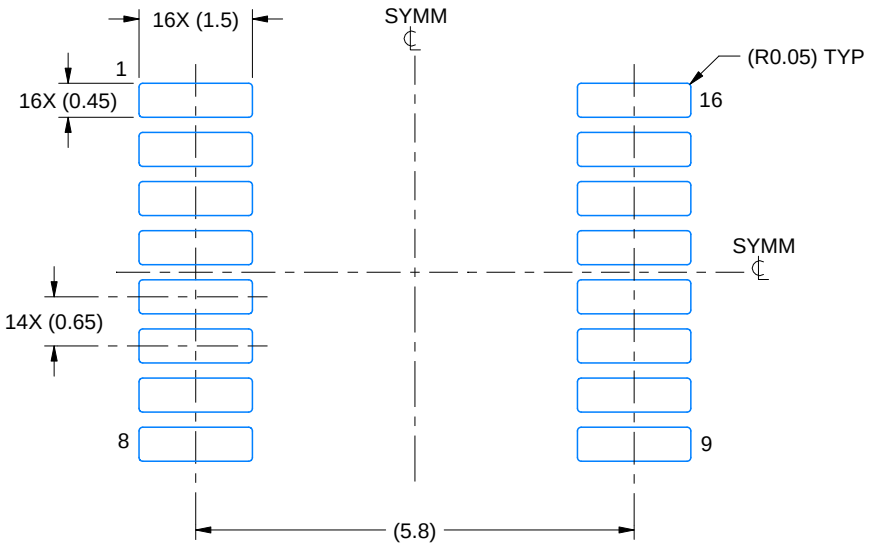
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



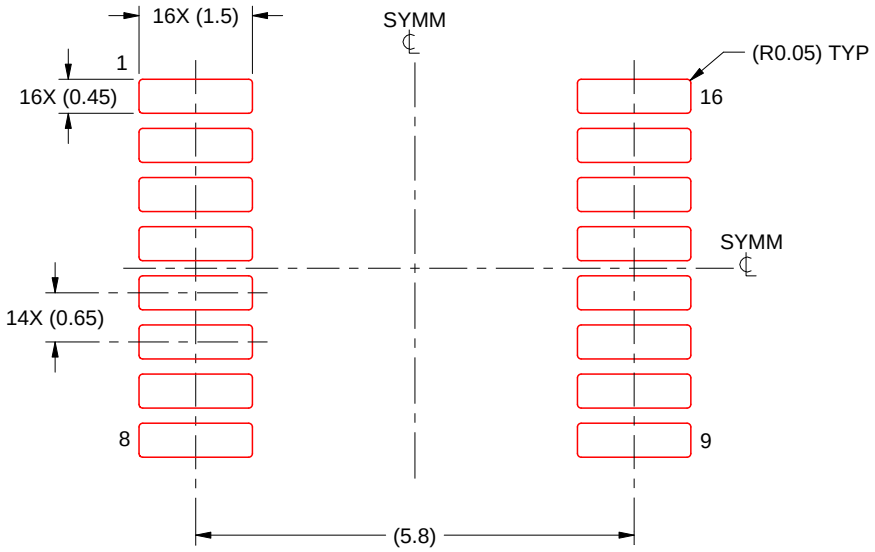
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

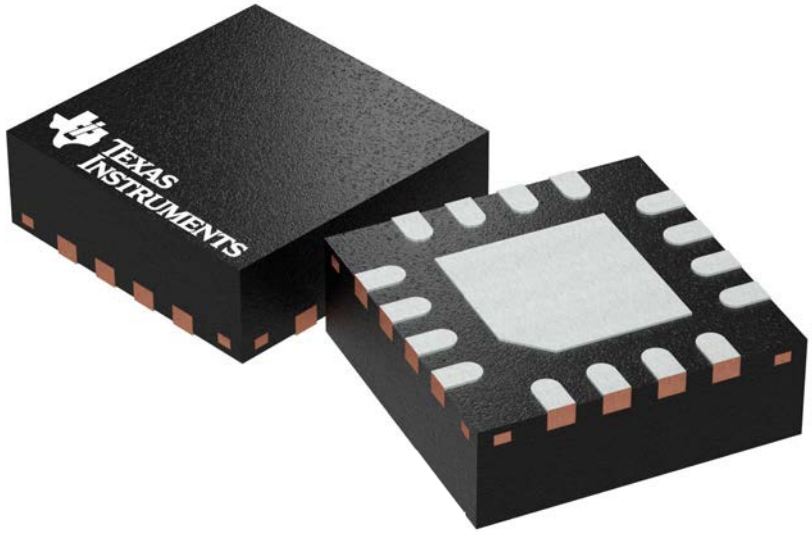
4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

RGT 16 VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



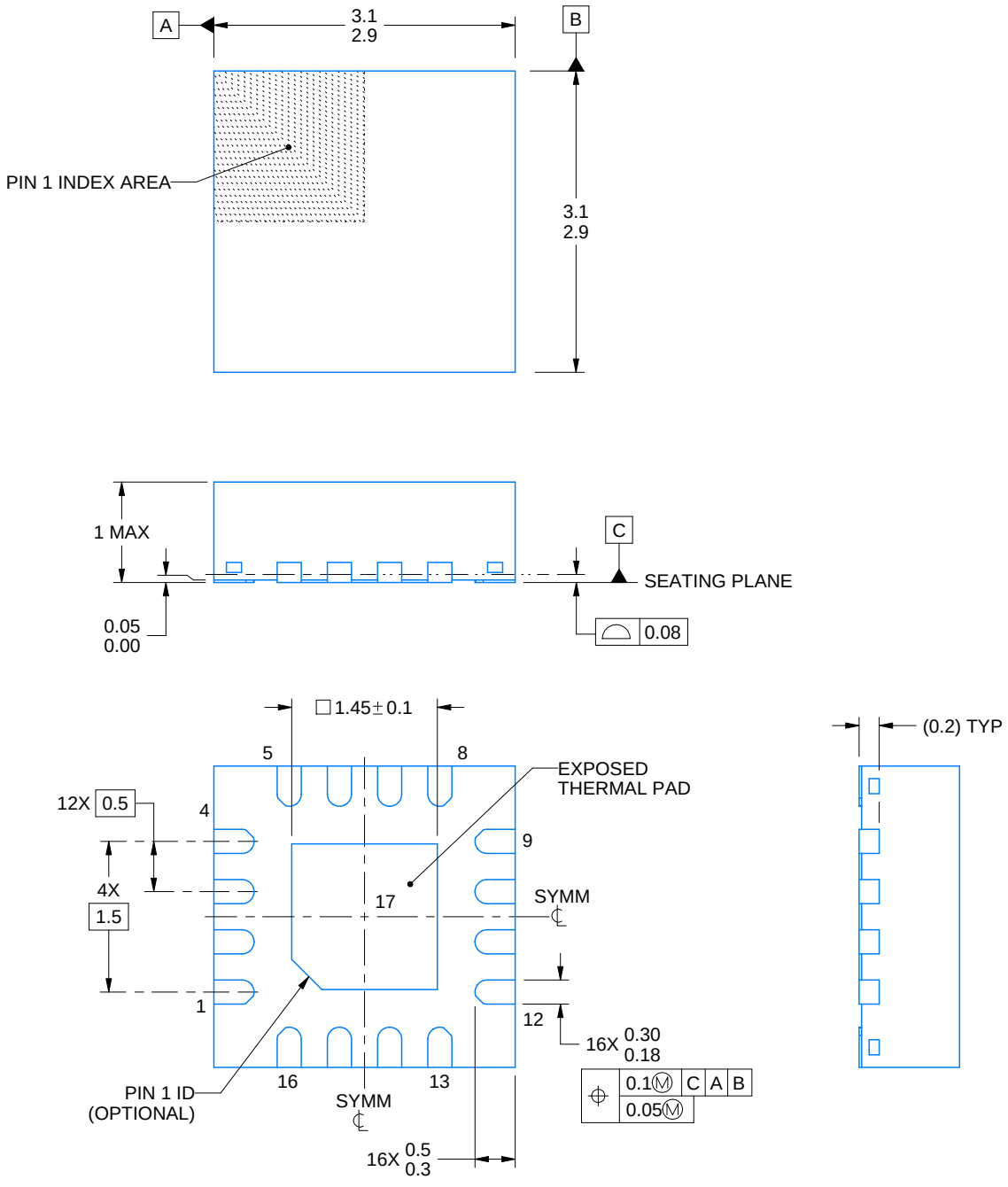
Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

RGT0016A

PACKAGE OUTLINE

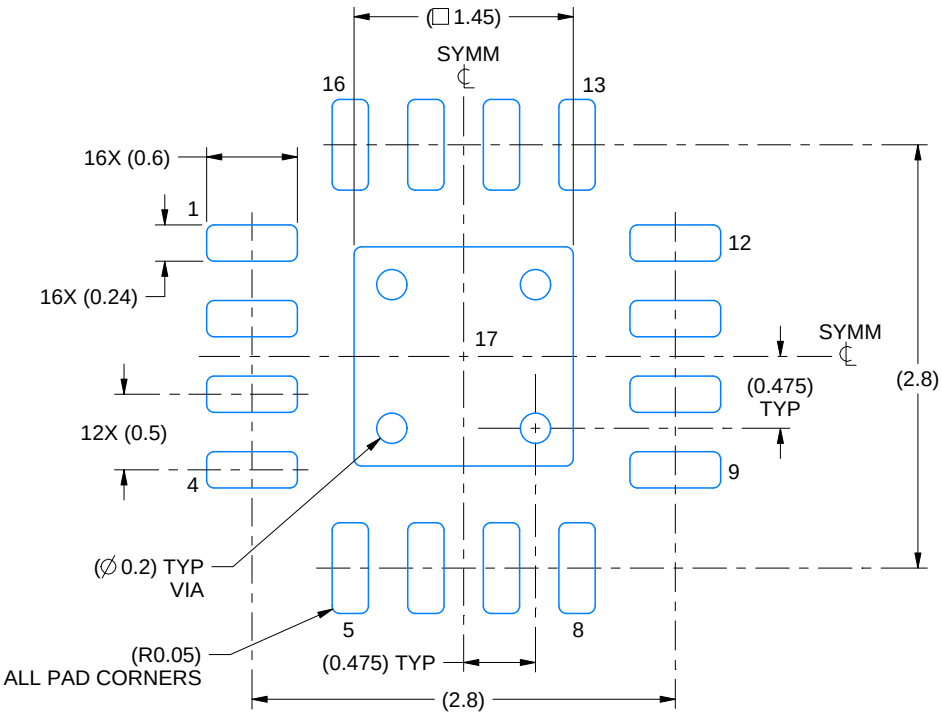
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

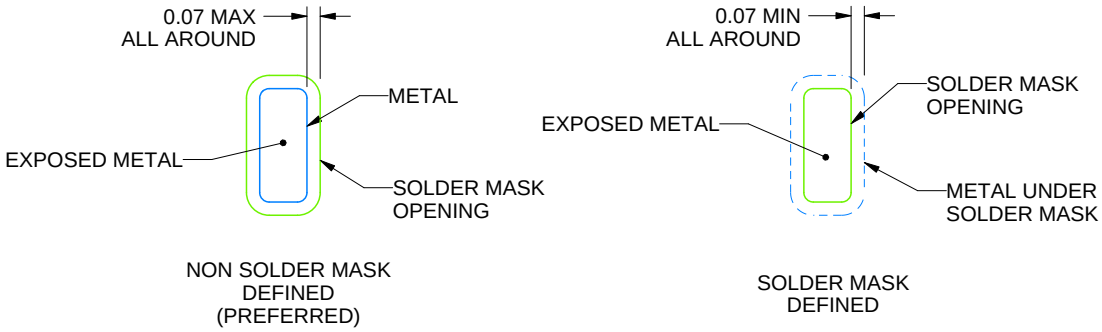


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. Reference JEDEC registration MO-220



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:20X

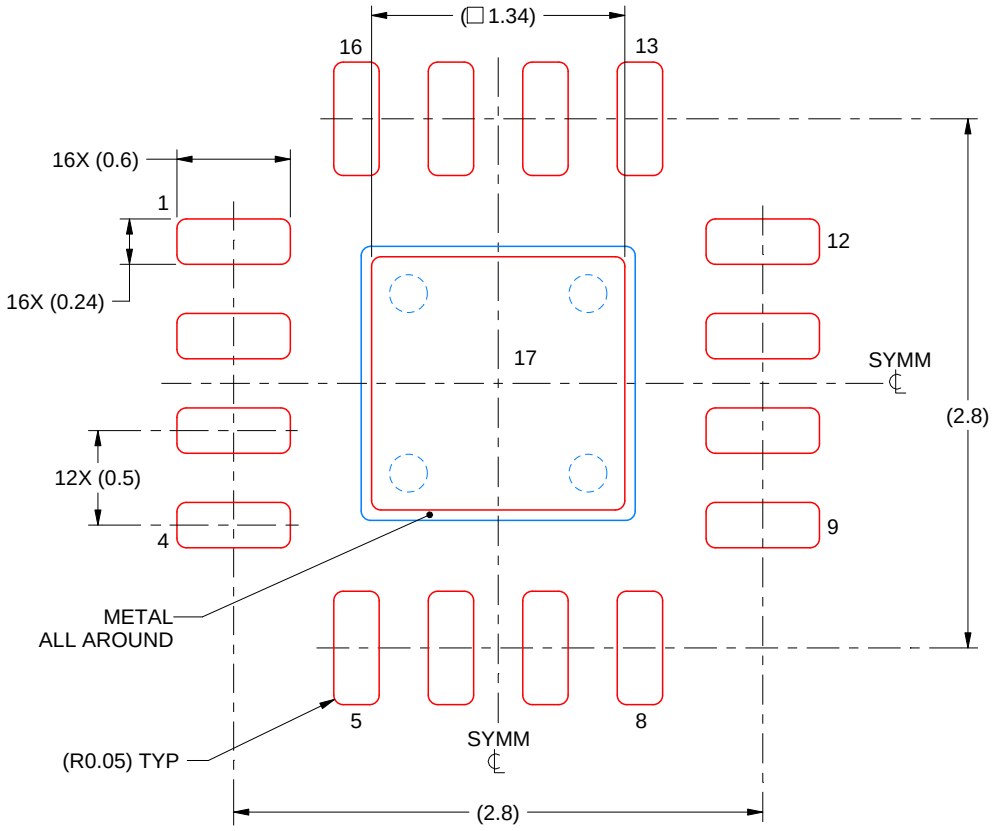


SOLDER MASK DETAILS

4219032/A 02/2017

NOTES: (continued)

5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
6. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 17:
86% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:25X

4219032/A 02/2017

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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